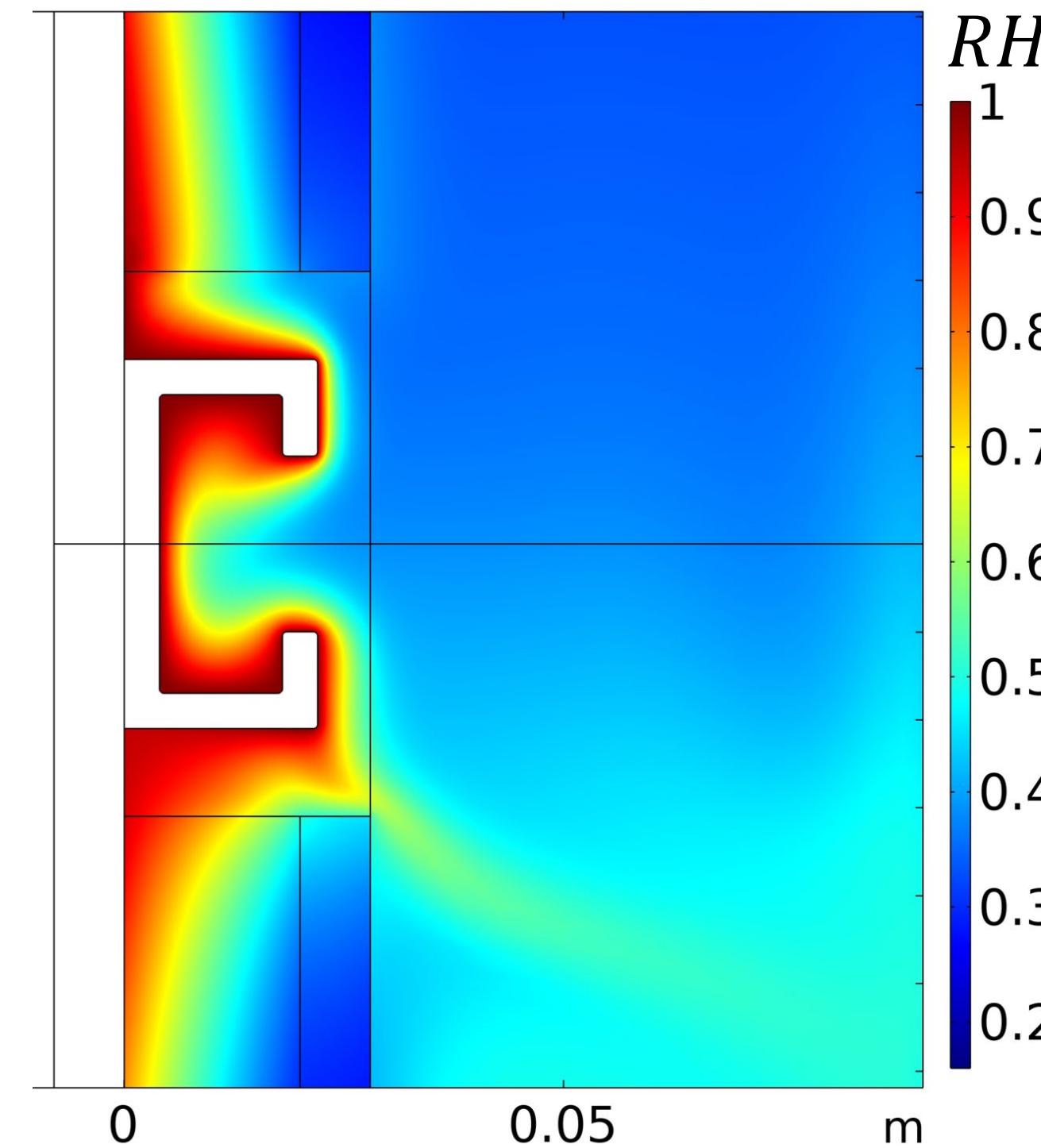


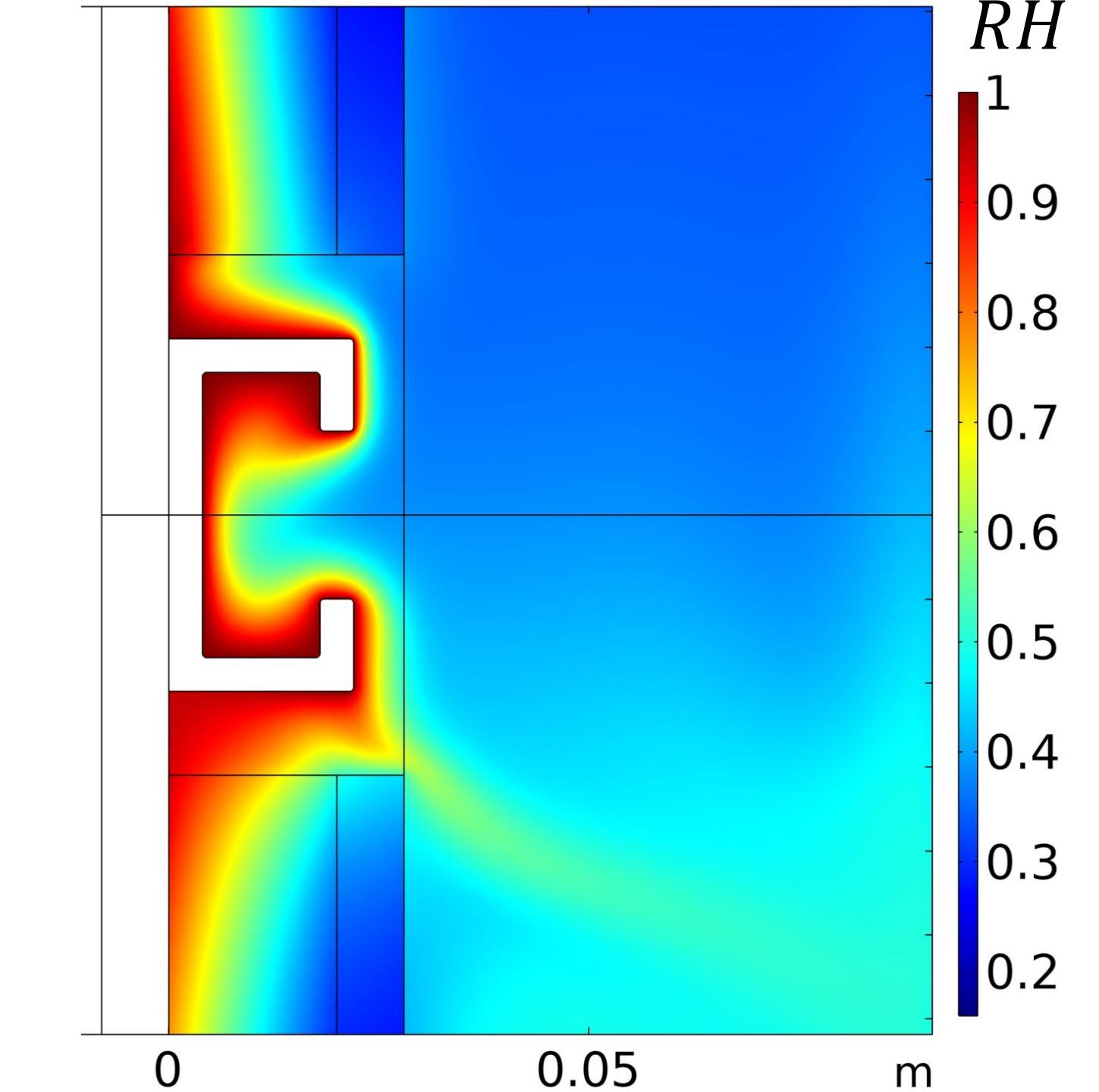
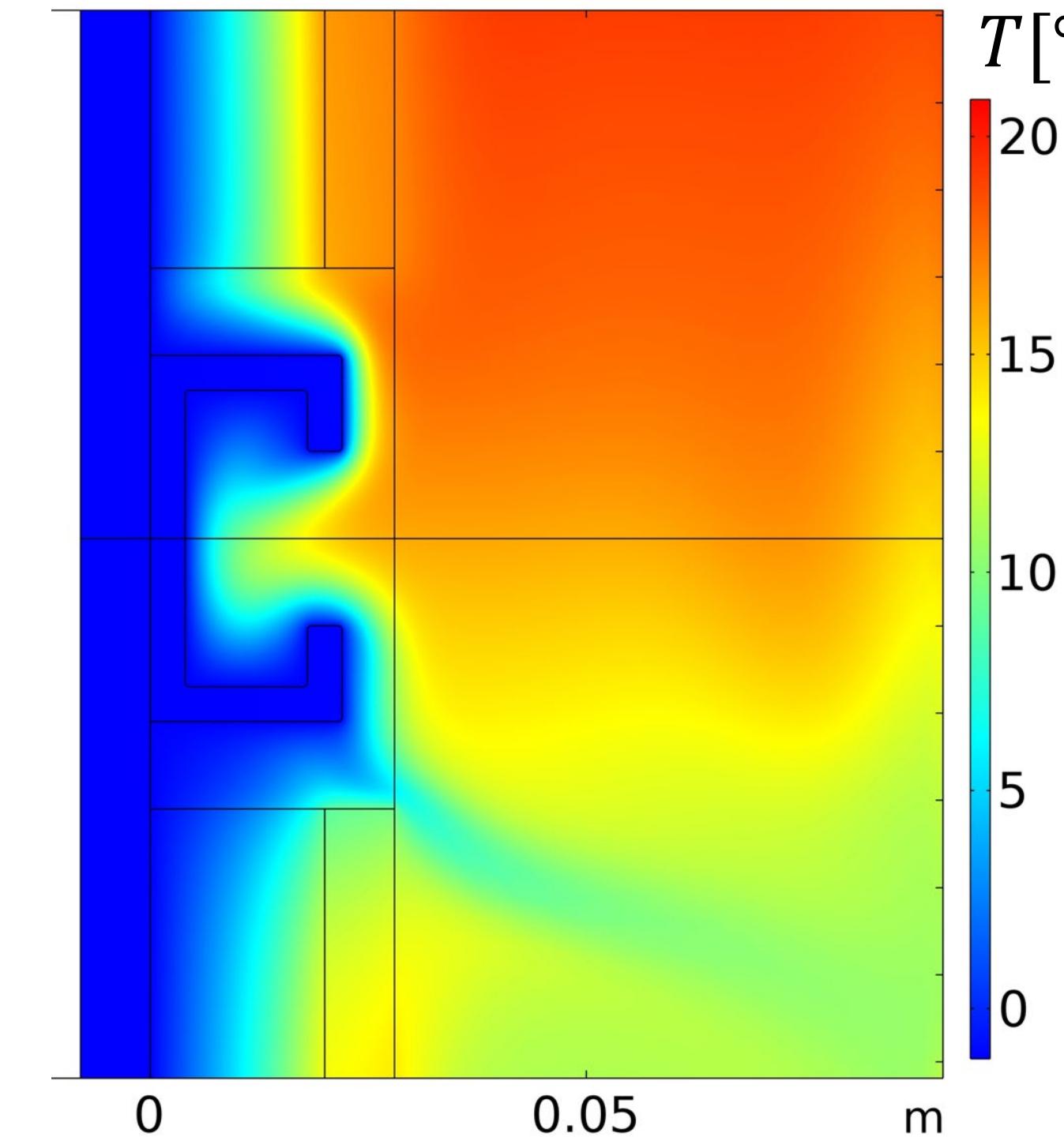
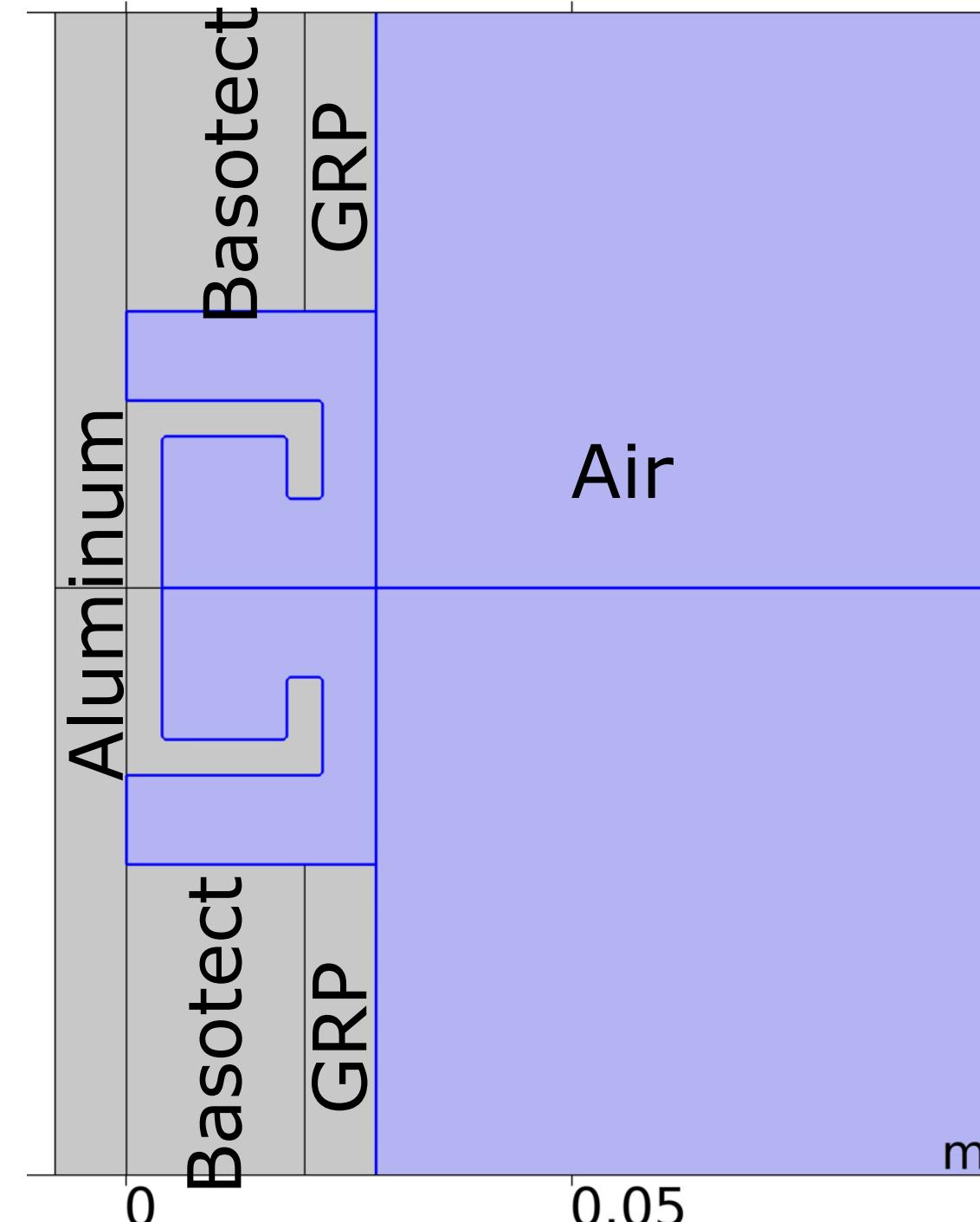
# Simulating condensate layers on thermal bridges in train walls

Felix Lüönd and Tom Graf

**Engineering and Architecture**  
November 14, 2023

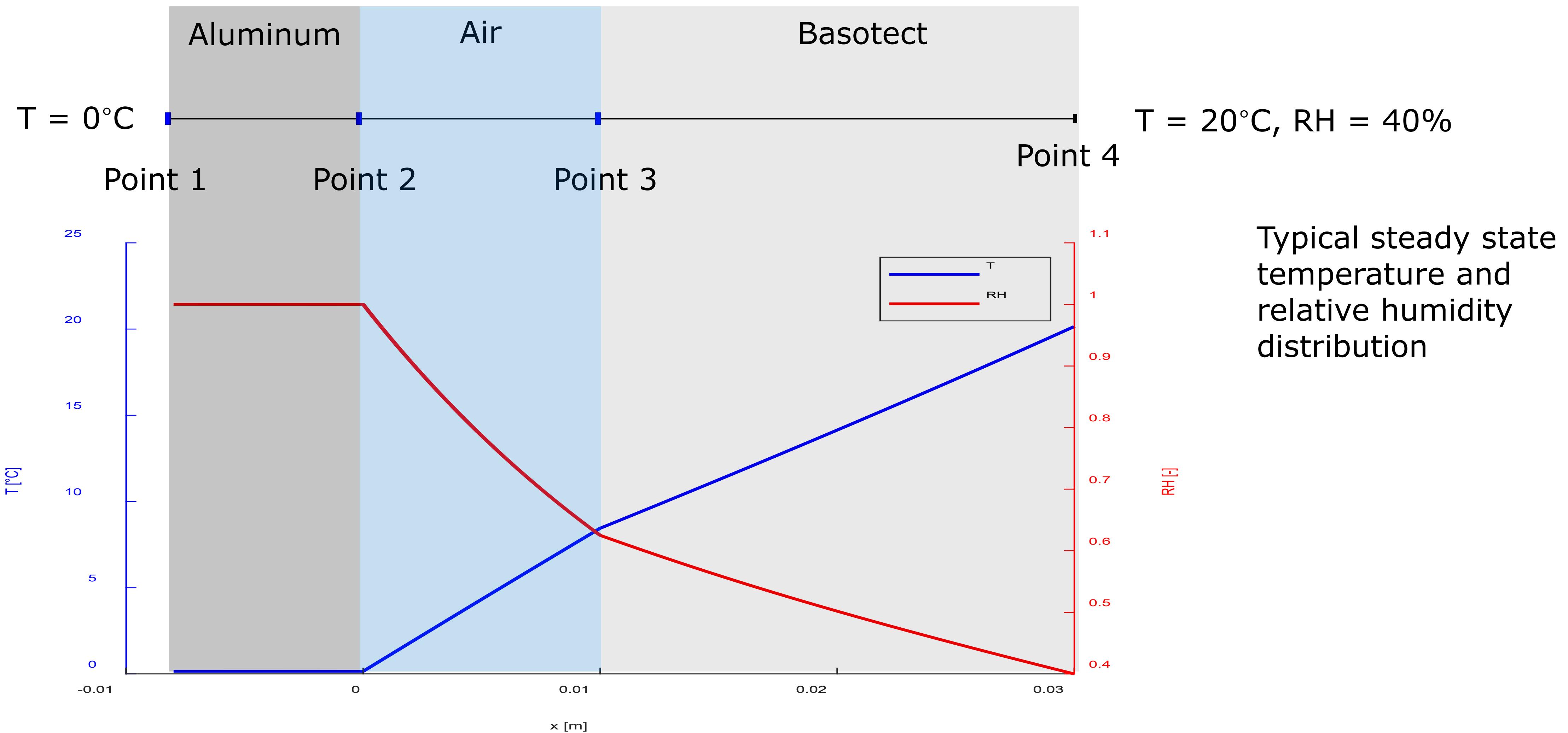


Goal: Calculate the amount and distribution of water condensing on the surface of thermal bridges in train walls.



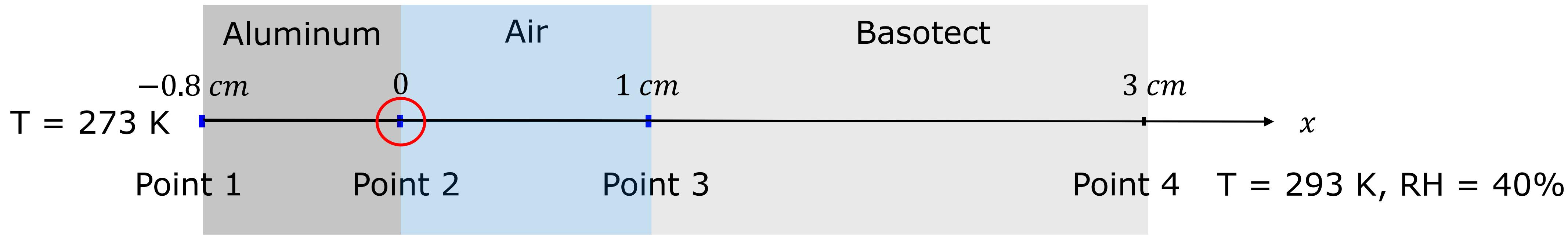
- C-rack as an example of a frequent thermal bridge in train walls
- C-rack usually has direct thermal contact to the metallic hull of the car body
- C-rack is in contact with the warm cabin air
- → high relative humidity and condensing moisture on the surface of the C-rack.

# 1D test case for different models with purely diffusive moisture transport



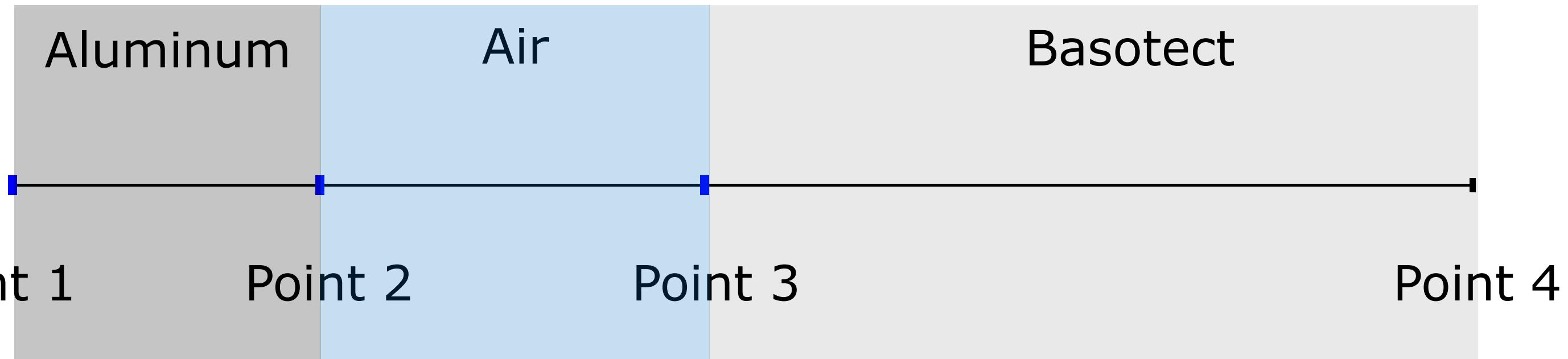
# Three ways to implement a condensed water layer in COMSOL

1D test case for different layer growth models: Purely diffusive moisture transport



1. COMSOL provided: «Moist surface» node in the «Moisture Transport in Building Materials» physics
2. Custom model: «Film growth model», calculate condensate layer thickness from vapor flux with custom ODE
3. Custom model: «Sponge model», air layer modeled as a Building material with artificial moisture capacity

# 1. COMSOL provided: «Moist surface» node



- Requires a «Moist air» node within «Moisture transport in Building Materials» physics
- Designed to model convective moisture transport
- Evaporation only if a liquid layer exists
- Condensation only for RH>1
- Evaporation rate factor K for diffusive moisture transport:

$$K = -D \cdot \frac{dc_v}{dx} \cdot \frac{1}{c_{sat}(T) - c_v} \rightarrow g_{evap} = -M_v \cdot D \cdot \frac{dc_v}{dx}, \quad \text{if } c_v > c_{sat} \text{ or } c_l > 0$$

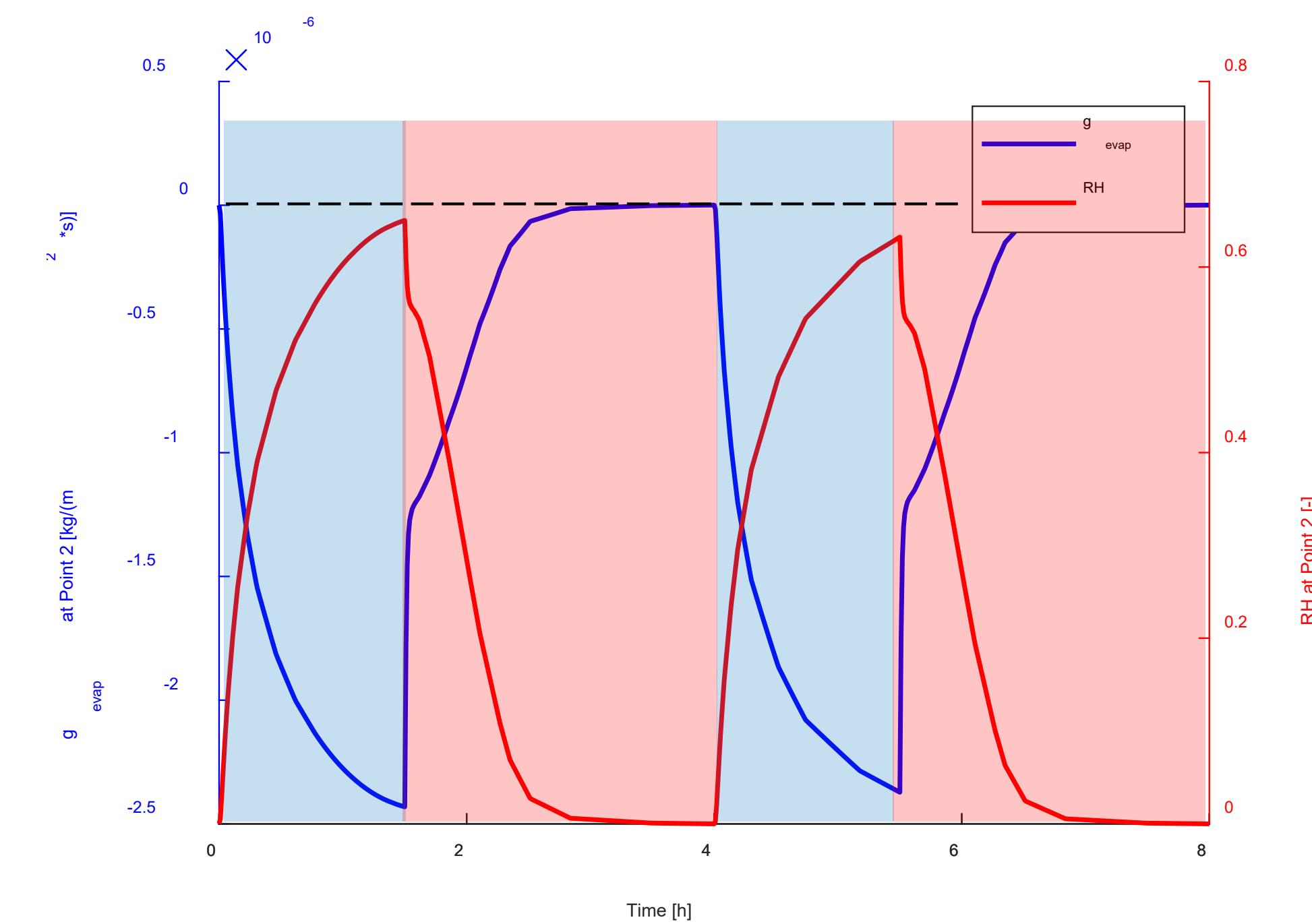
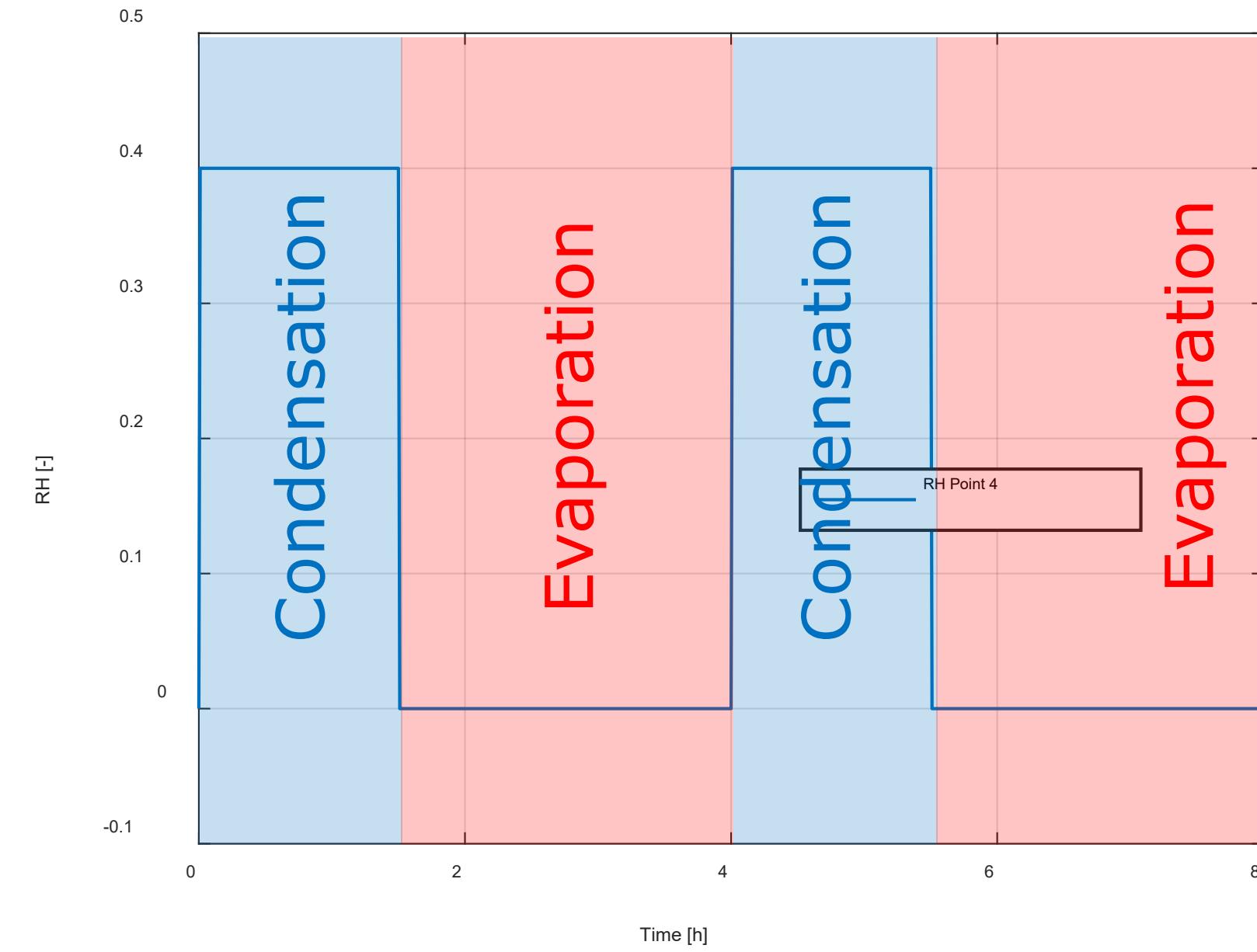
- Moisture Transport in Building Materials (mt)
- ▷ Building Material 1
  - ▷ Initial Values 1
  - ▷ Insulation 1
  - ▷ Moisture Content 1
  - ▷ Moist Air 1
  - ▷ Moist Surface 1

$$-\mathbf{n} \cdot \mathbf{g}_w = A_c g_{evap}$$

$$g_{evap} = \begin{cases} M_v K(c_{sat} - c_v) & \text{if } c_v > c_{sat} \text{ or } c_l > 0 \\ 0 & \text{otherwise} \end{cases}$$

$$M_v \frac{\partial c_l}{\partial t} = -A_c g_{evap}, \quad c_l(0) = c_{l,init}$$

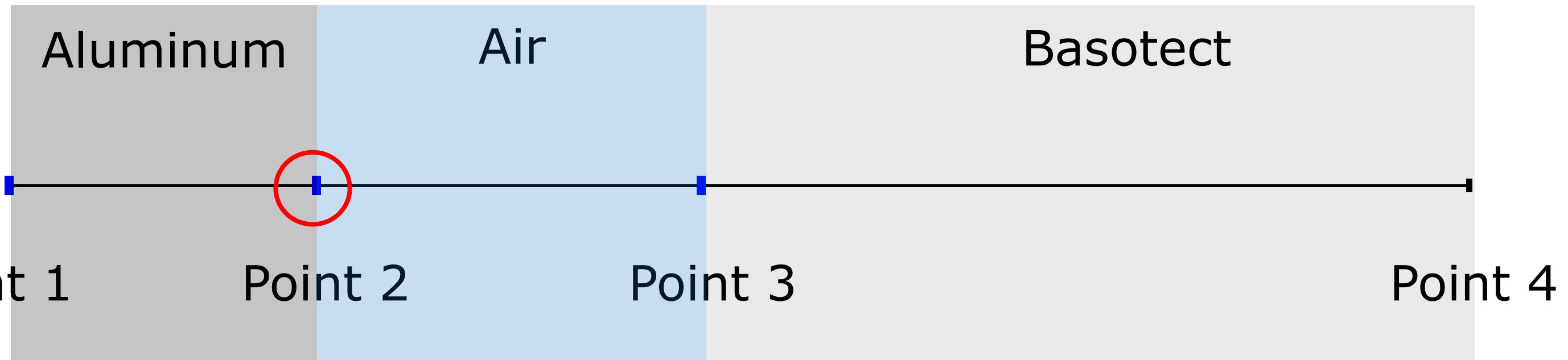
# 1. «Moist surface» node: Test with condensation/evaporation cycles



- Vapor flux  $g_{evap} \neq 0$ , despite  $RH < 1$  and  $c_{liq,ini} = 0$
- Vapor flux  $g_{evap} < 0$  always, despite  $RH < 1$
- $c_{liq} = 0$ , despite  $g_{evap} < 0$

Eroneous and inconsistent results?!

## 2. Custom model: «Film growth model»



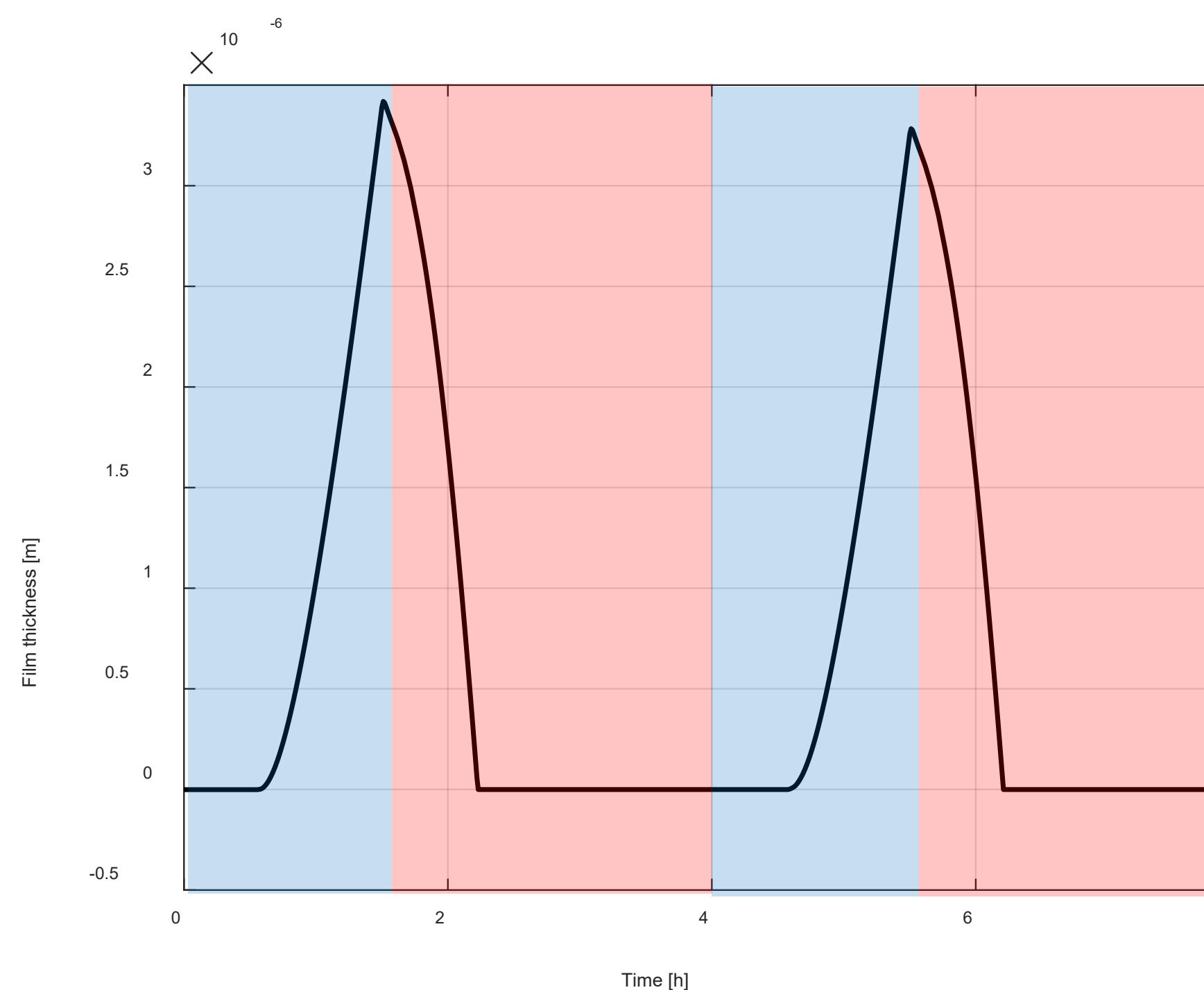
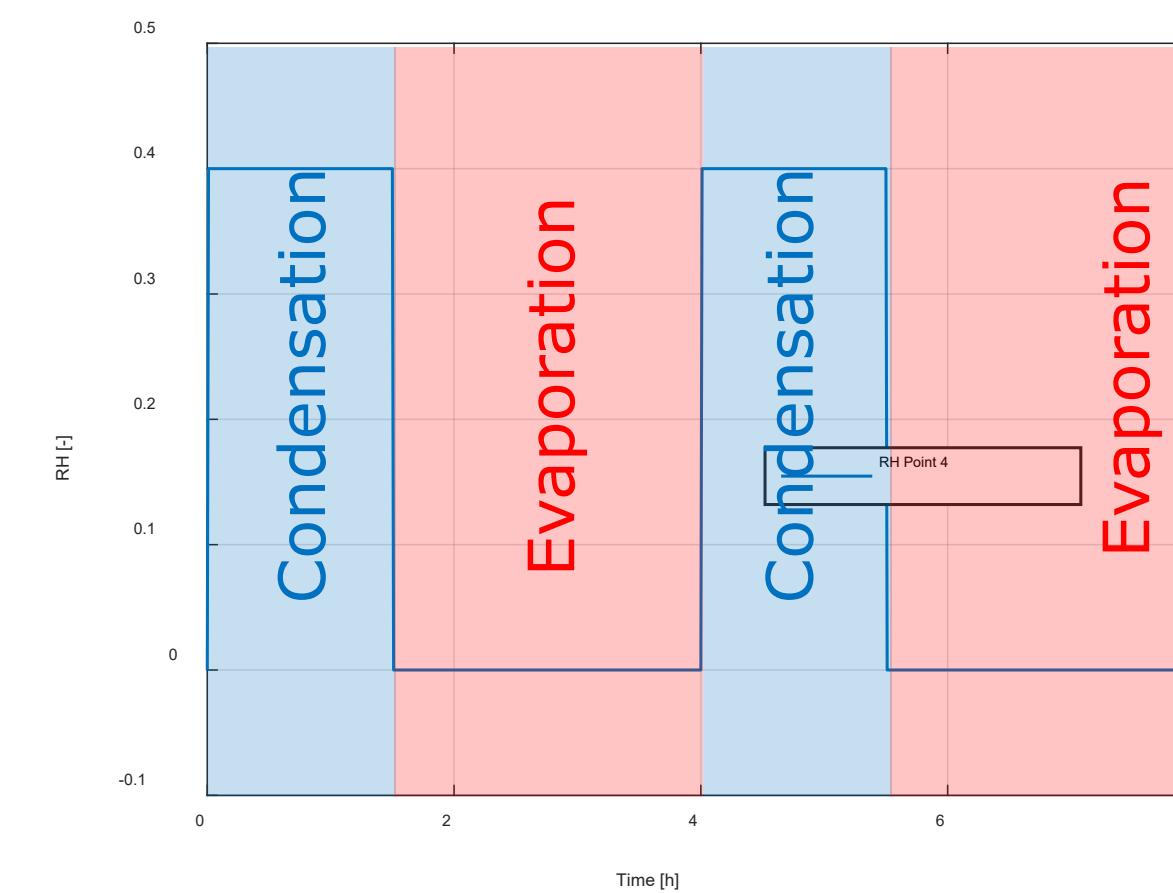
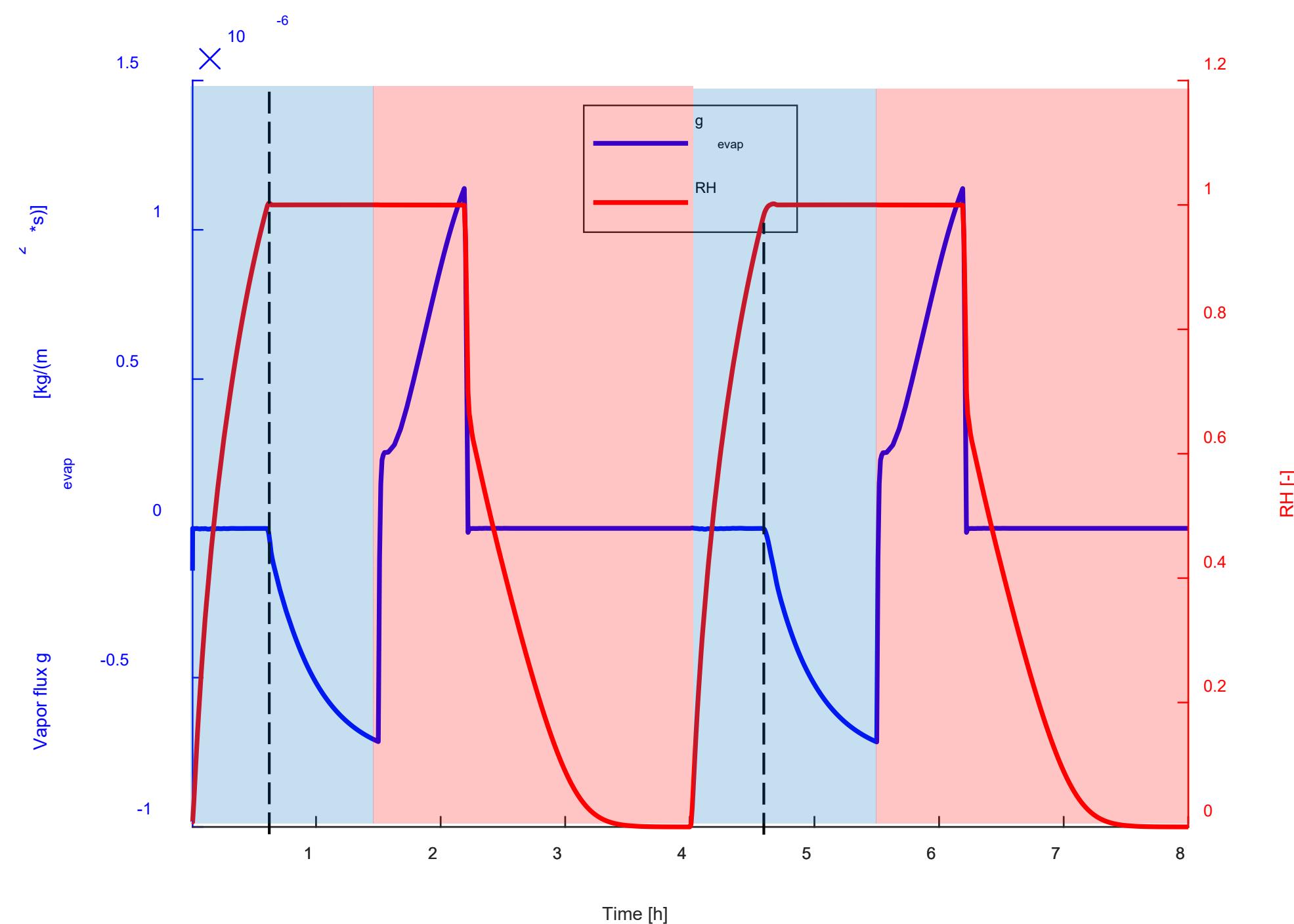
- Water condensation on cold wall boundary (Point 2)
- 2 weak inequality constraints at Point 2 to impose that:
  - $\phi \leq 1$
  - $\phi = 1$  if  $d_{film} > d_0$  with  $d_0 = 10^{-9}m$
- Model solves for dependent variable  $d_{film}$  defined by ODE:

$$\frac{d d_{film}}{dt} = \left( \theta(\phi - 1) + \theta(d_{film}) \cdot (1 - \theta(\phi - 1)) \right) \cdot \frac{1}{\rho} (-\delta_p \vec{\nabla} p_v \cdot \vec{n})$$

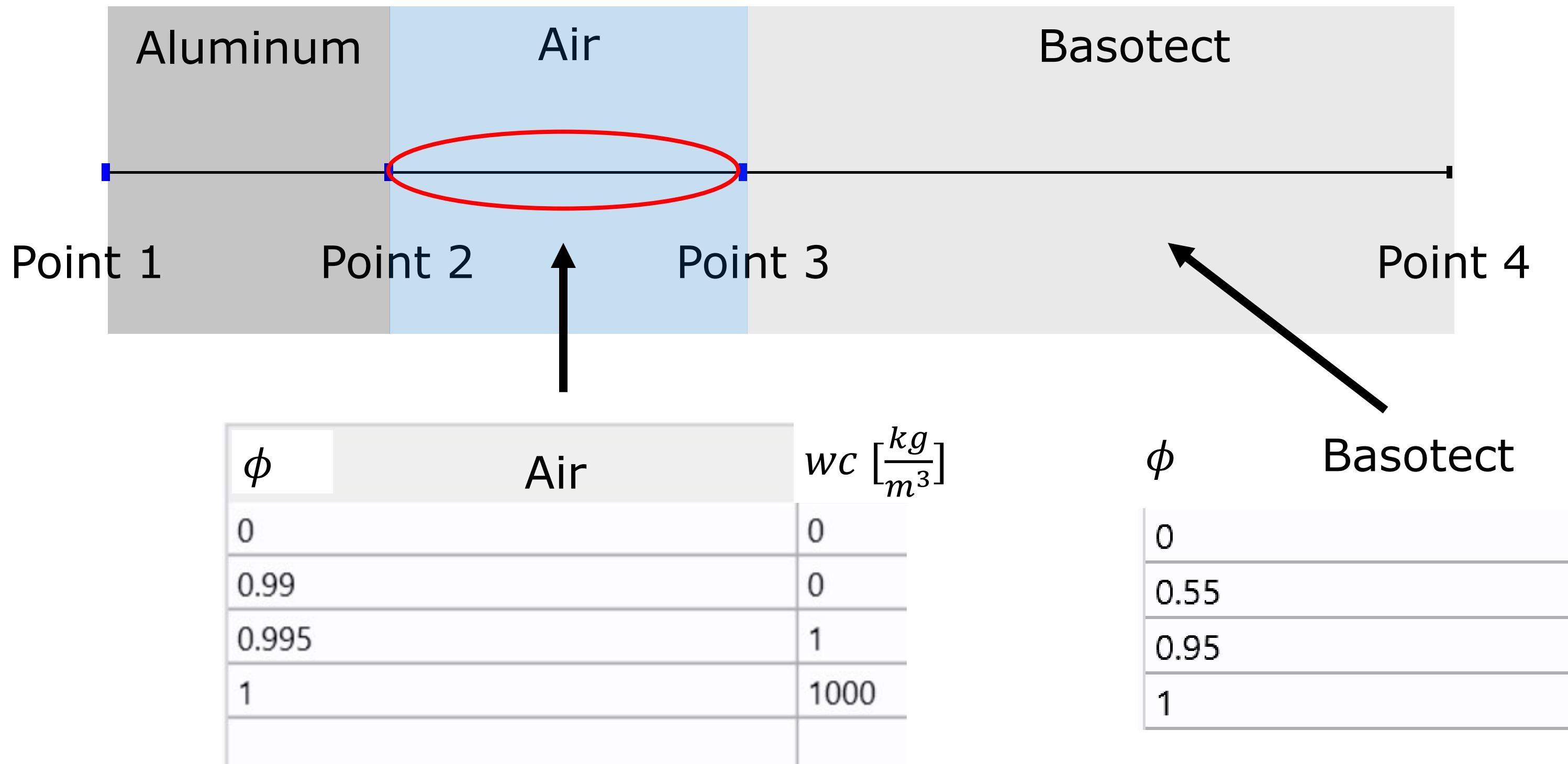
$$\theta(x) = \begin{cases} 0, & x < 0 \\ 1, & x > 0 \end{cases}$$

## 2. Custom model: «Film growth model»

- Relative humidity at point 2 is limited to  $RH = 1$ , and consistent with the vapor flux.
- $RH = 1$  persists into the evaporating period due to the existence of a liquid film

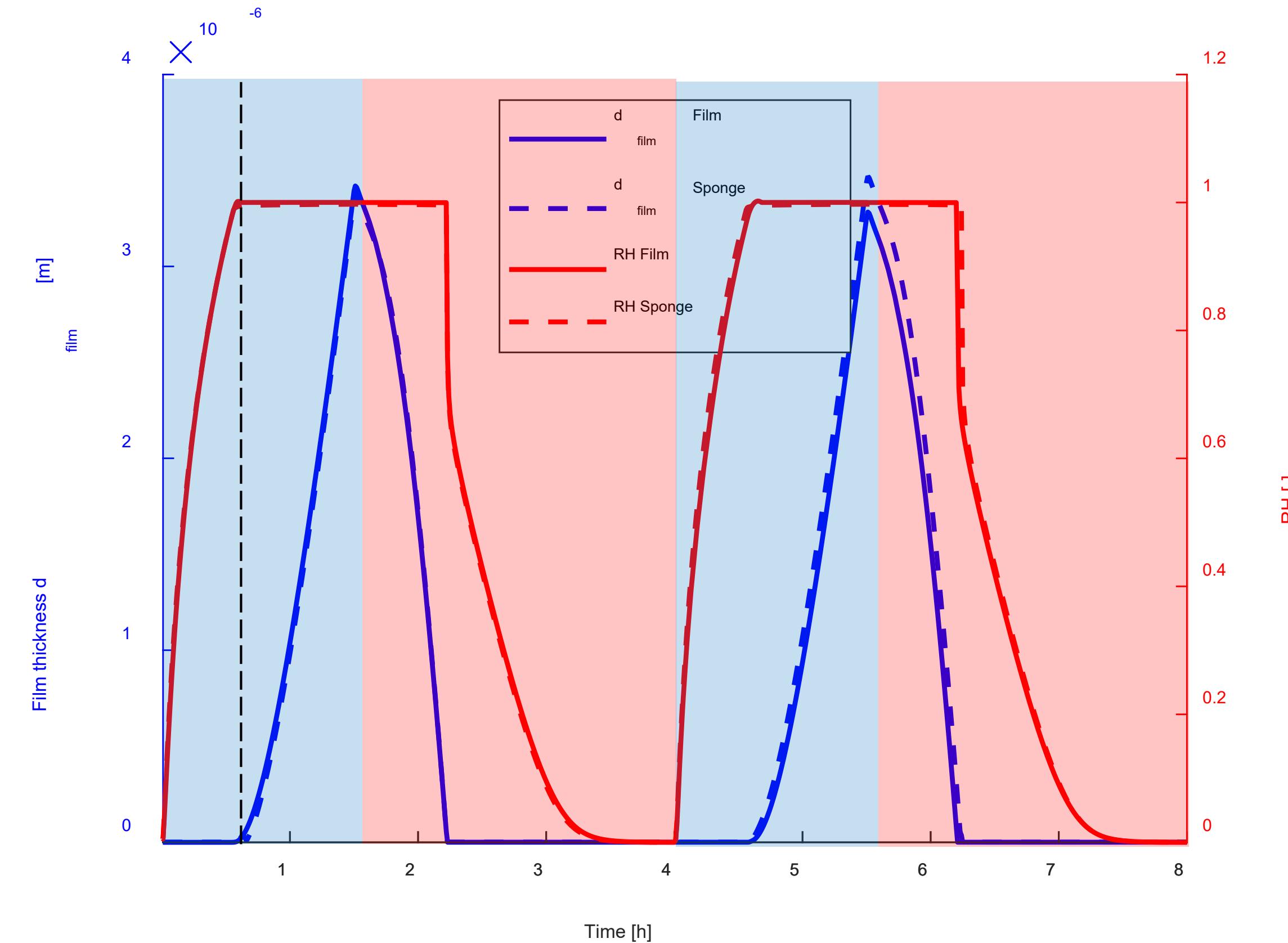


### 3. Custom built: «Sponge model»



- Water condensation within the «Air» domain
- Air modeled as a porous building material with an **artificial moisture capacity function**  $wc(\phi)$
- Water film thickness  $d$  calculated from moisture content  $c_w$  [ $\frac{mol}{m^3}$ ]: 
$$d = \frac{M_w}{\rho} \int_{Point\ 2}^{Point\ 3} c_w(x) dx$$

## «Film growth model» vs. «Sponge model»



- Good agreement between «Film model» and «Sponge model».
- Both models are able to predict the amount of water condensed on a surface.

## «Film model» vs «Sponge model»

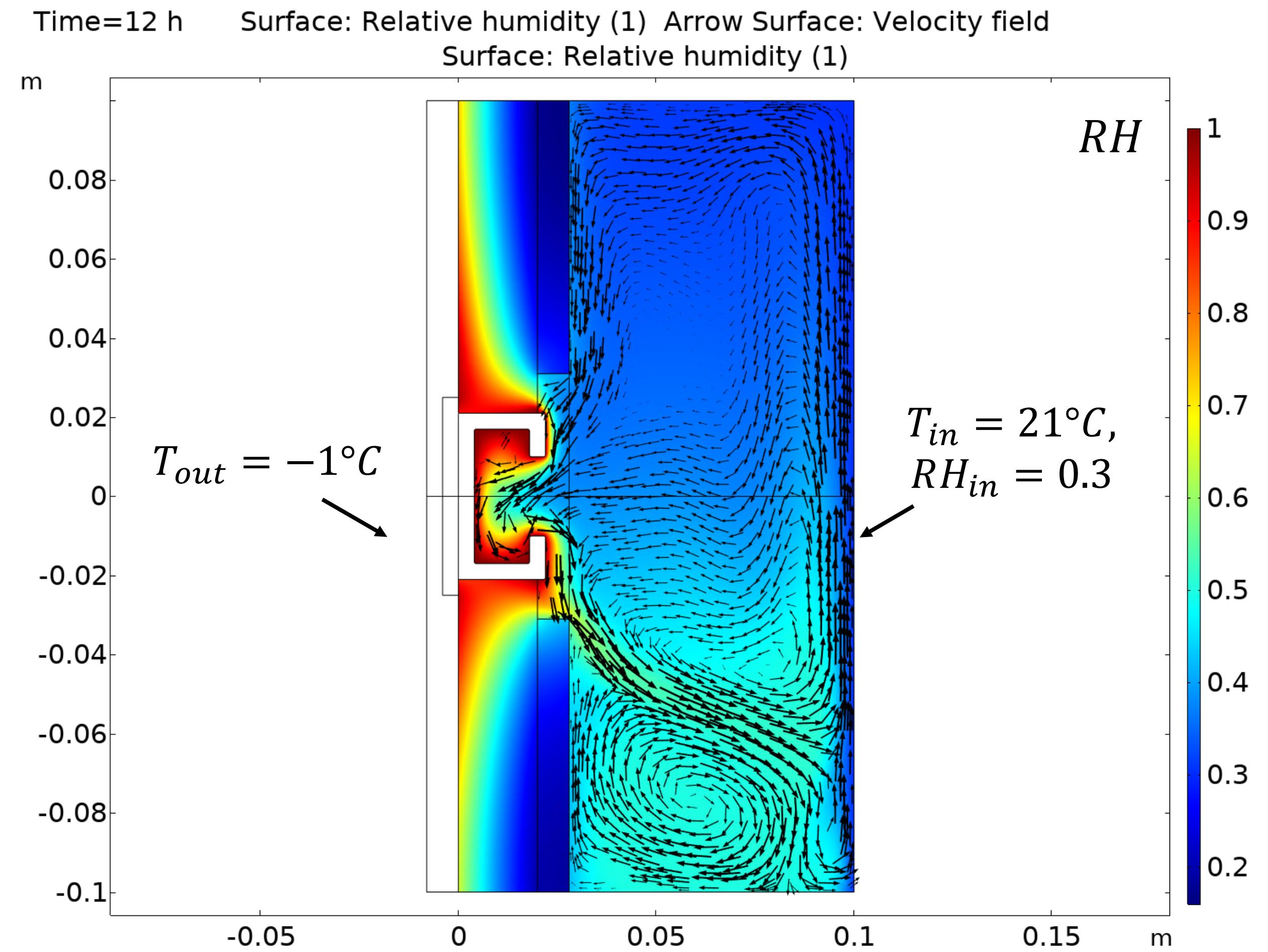
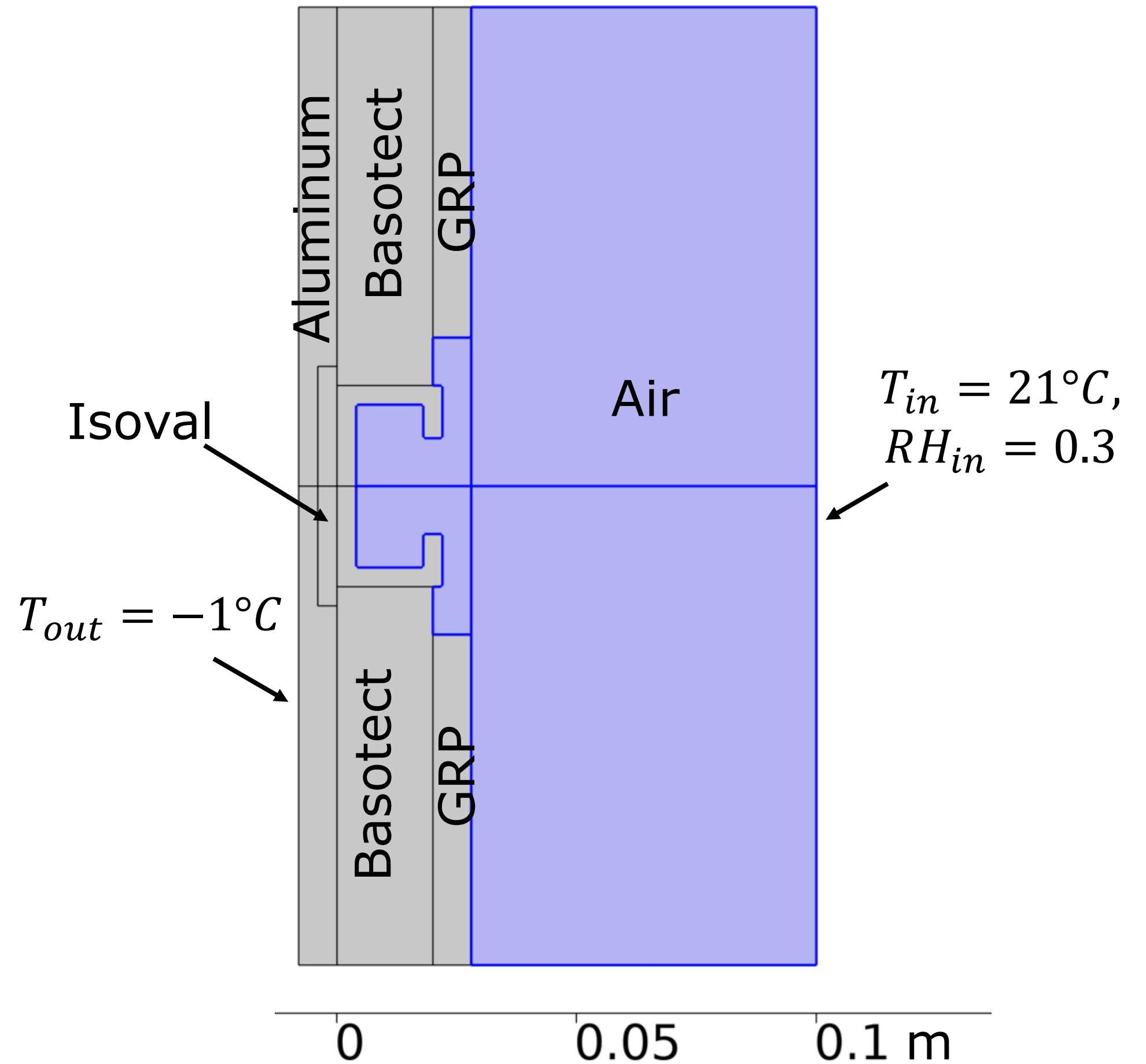
	<b>2. Film growth model</b>	<b>3. Sponge model</b>
Advantages	<ul style="list-style-type: none"><li>• Direct calculation of <math>d_{film}</math></li><li>• close representation of the physics</li><li>• Possible to combine with transport by convection</li></ul>	<ul style="list-style-type: none"><li>• Easy to implement</li><li>• No constraints necessary</li></ul>
Disadvantages	<ul style="list-style-type: none"><li>• Increased model complexity: +1 ODE, +2 constraints</li><li>• Evaporation requires very small timesteps in 2D</li><li>• Neglects the influence of condensed moisture on conductive heat transport</li></ul>	<ul style="list-style-type: none"><li>• Not possible to combine with transport by convection</li><li>• <math>d_{film}</math> difficult to calculate in 2D</li><li>• Sensitivity to the arbitrary definition of <math>wc(\phi)</math> in 2D</li><li>• Neglects the influence of condensed moisture on conductive heat transport</li></ul>



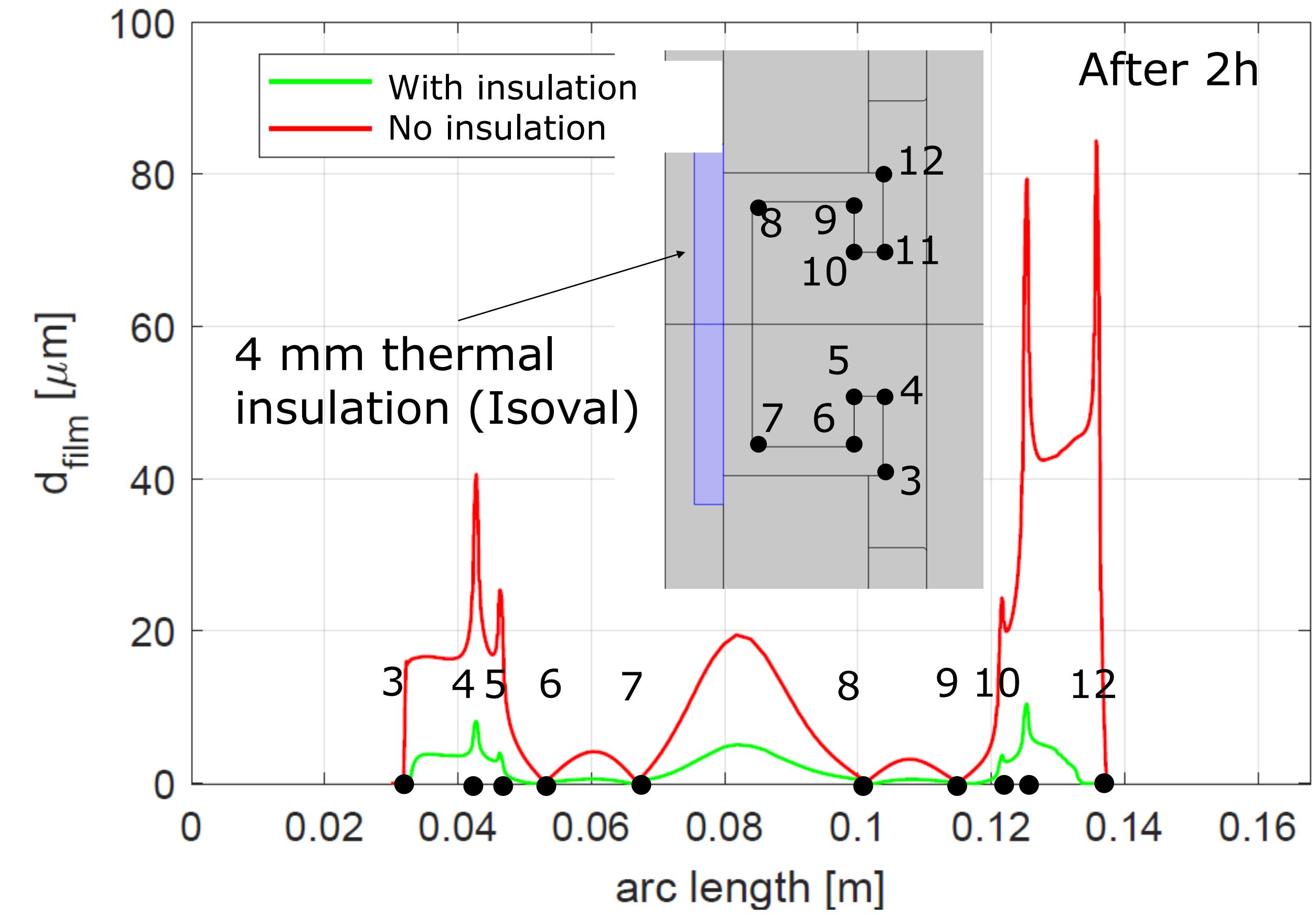
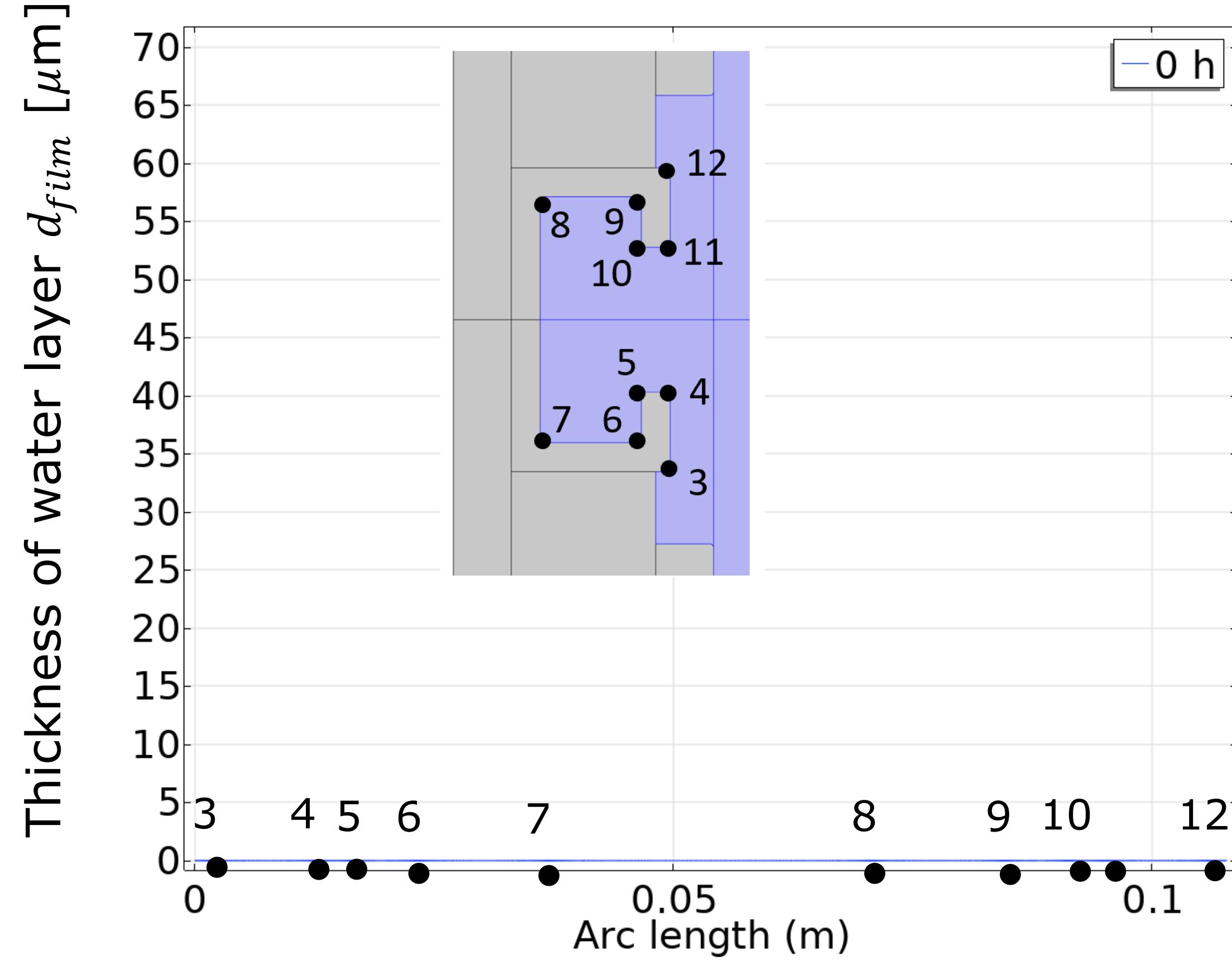
Film growth model has been selected to calculate condensation on thermal bridges in 2D and 3D.

# 2D Sim. of condensation on a thermal bridge in train walls using «Film growth model»

Winter scenario with constant boundary conditions:  $T_{out} = -1^{\circ}C$ ,  $T_{in} = 21^{\circ}C$ ,  $RH_{in} = 30\%$



# 2D Sim. of condensation on a thermal bridge in train walls using «Film growth model»



- Convection dominates water vapor transport over diffusion.
- Droplets running from the surface of a thermal bridge have to be expected after  $\sim 10$  h in a winter scenario.
- Thermal insulation of the thermal bridge substantially reduces the amount of condensing water.
- Condensation is most pronounced at protruding edges and corners.

# Conclusions

- The COMSOL preset «Moist surface» node has not yielded plausible results for the growth and evaporation of a condensate layer.
- Two different custom approaches («Film growth model» and «Sponge model») have been successfully tested in 1D with nearly identical results for the resulting condensate film thickness.
- The «Film model» has been coupled to CFD to include convective moisture transport in 2D simulations of condensation on a thermal bridge in train walls:
  - o Convection dominates water vapor transport over diffusion.
  - o Droplets running from the surface of a thermal bridge have to be expected after  $\sim 10$  h in a winter scenario.
  - o Thermal insulation of the thermal bridge substantially reduces the amount of condensing water.
- In 2D, the «Film model» is computationally very expensive in cases of evaporation, due to rapid changes in the ODE when  $d_{film} \rightarrow 0$ .

# Thank you!

**Lucerne School of Engineering and Architecture**

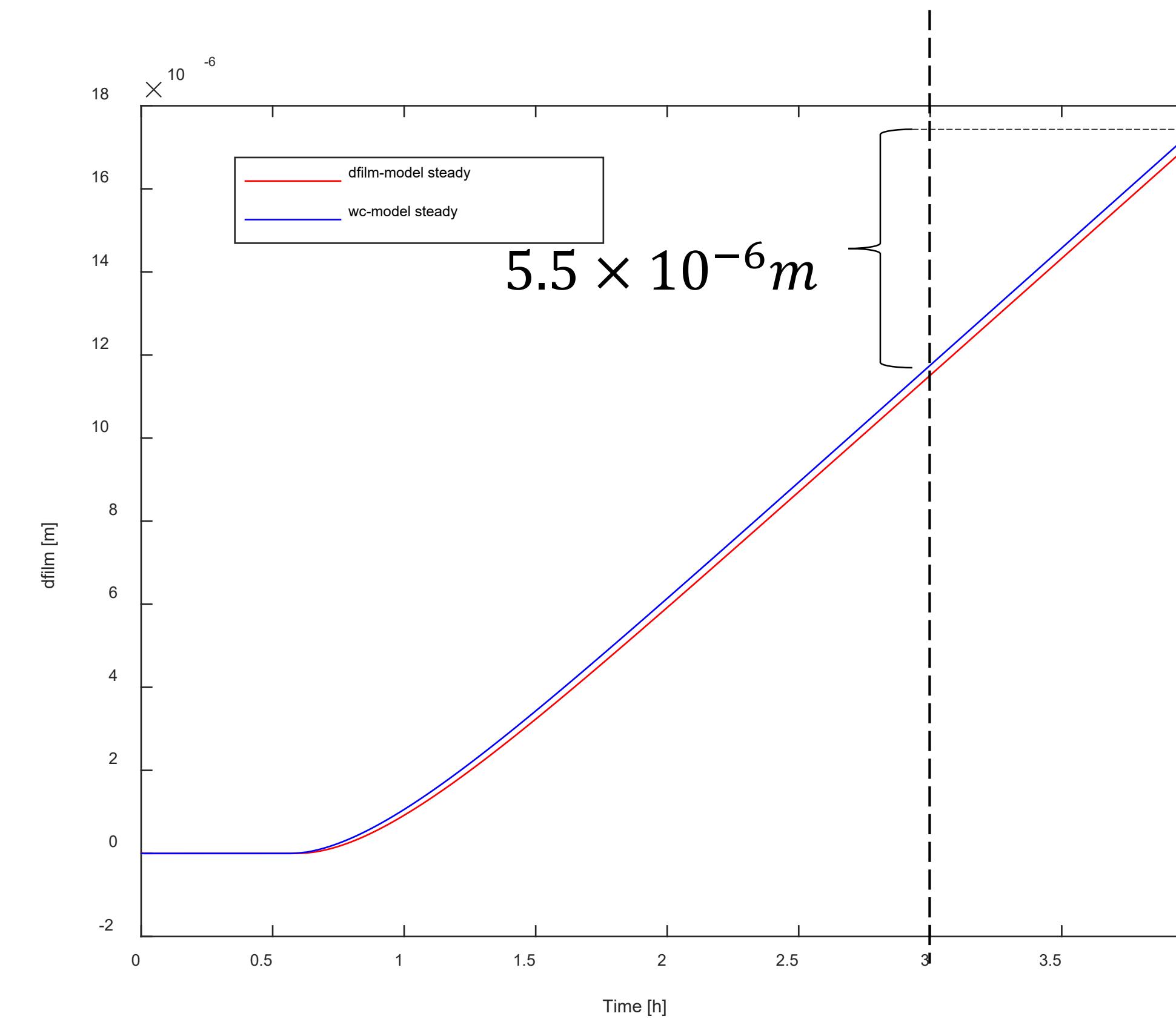
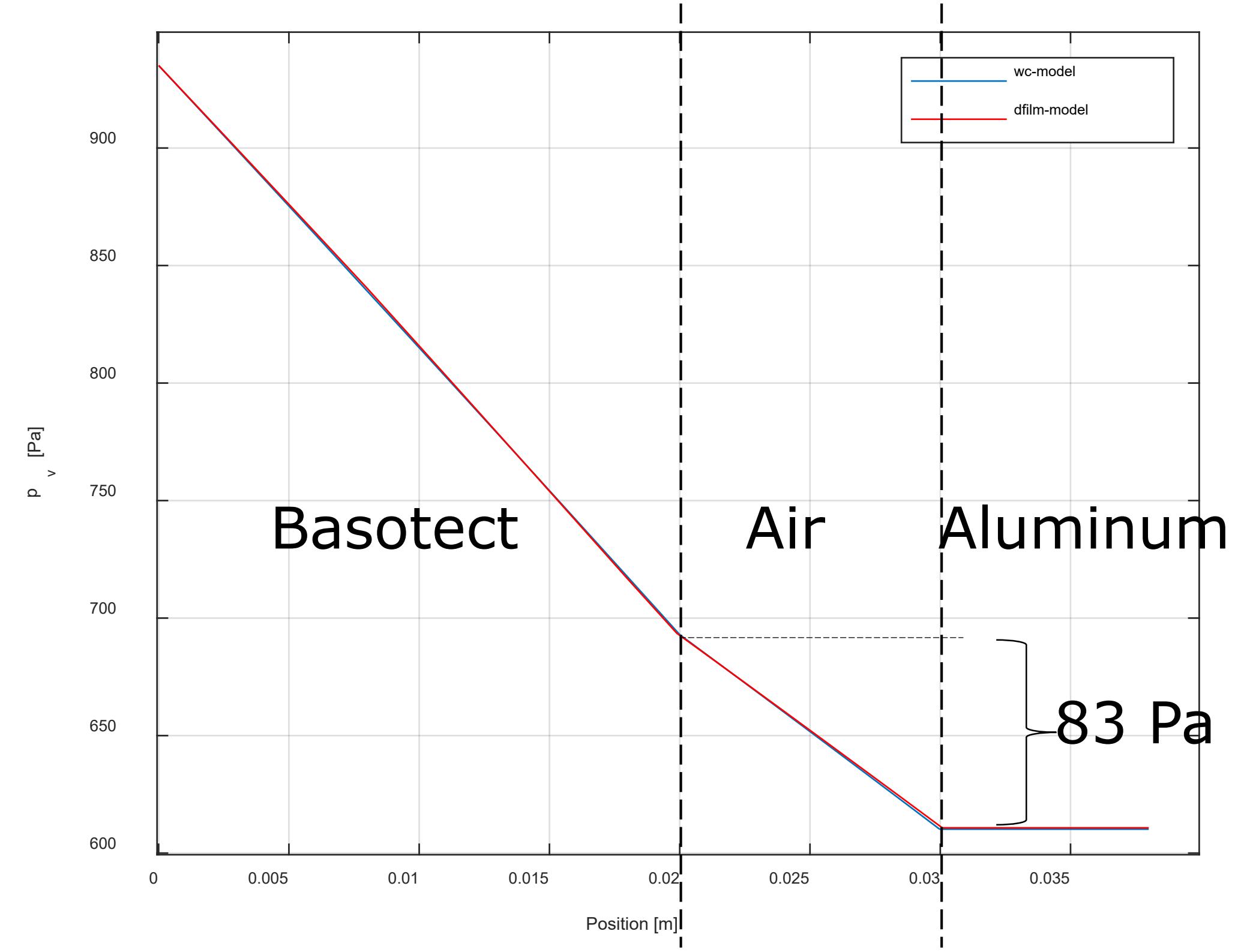
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**Prof. Dr. Tom Graf**

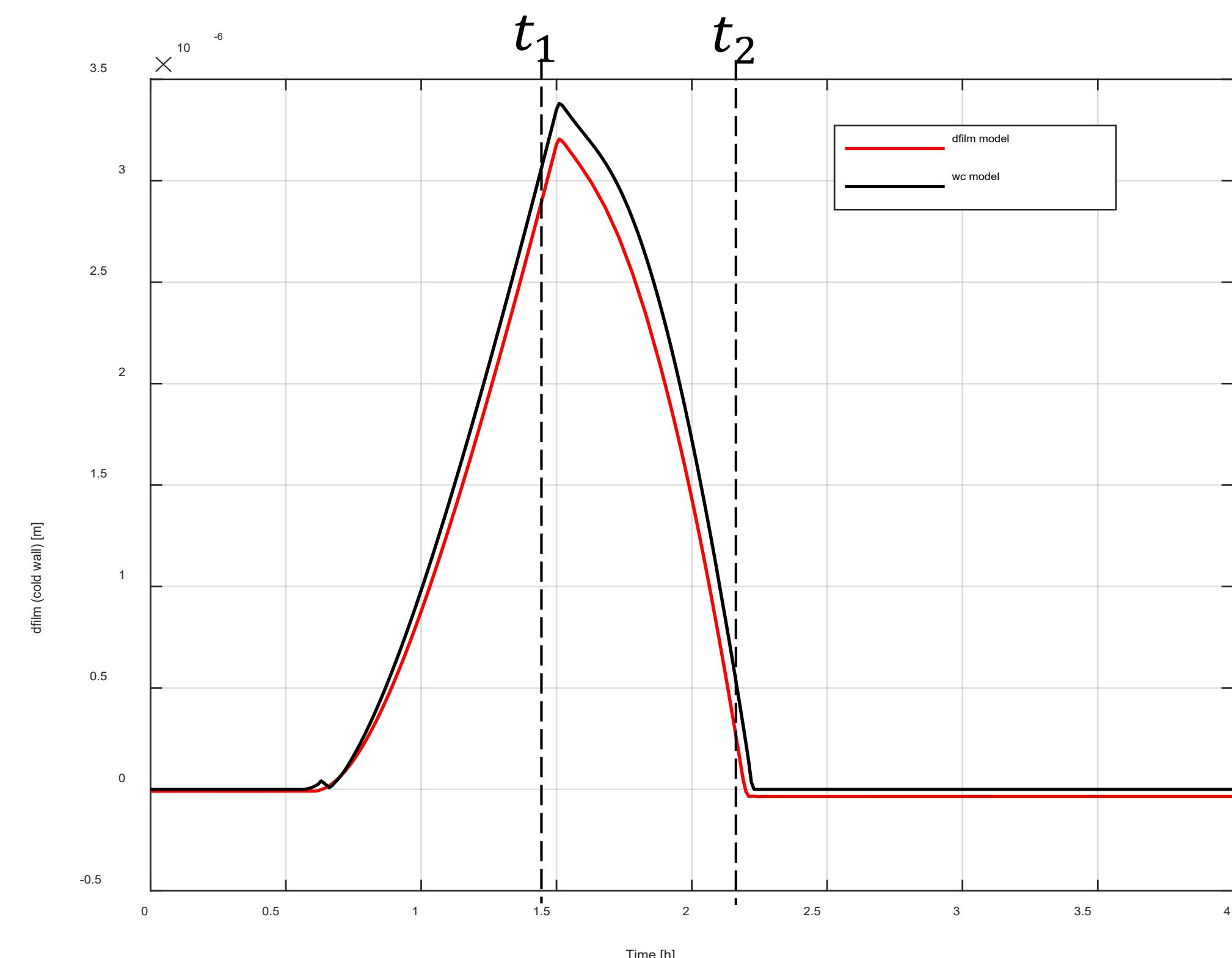
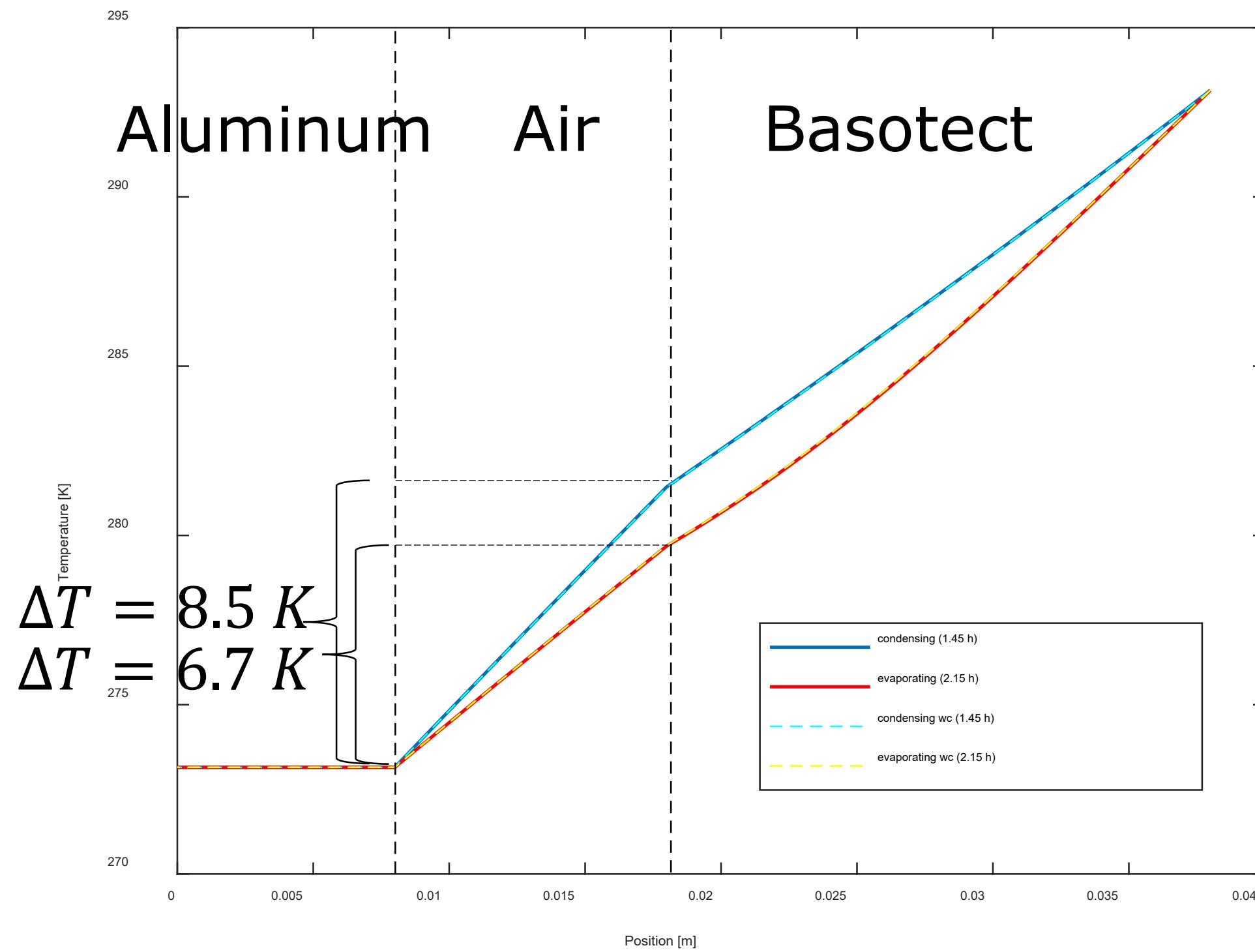
Phone direct +41 41 349 35 10  
[thomas.graf@hslu.ch](mailto:thomas.graf@hslu.ch)

# Annex



Validation of the growth rate of the water film for **steady** 40% RH on warm side (Point 4):

- Calculated from water vapor pressure gradient:  $\frac{d}{dt} d_{film} = -\frac{\delta_p \cdot \frac{d}{dx} mt.pv}{\rho} = -\frac{1.9 \times 10^{-10} s \cdot (-8300 \frac{Pa}{m})}{1000 \frac{kg}{m^3}} = 1.57 \times 10^{-9} \frac{m}{s}$   
where  $\delta_p = 2.01 \times 10^{-7} s \cdot T^{0.81} \cdot \frac{1}{p_{atm}} = 1.89 \times 10^{-10} s \dots 1.93 \times 10^{-10} s$  for T between 273 K ... 281 K
- Calculated from line integral of total water content (wc-model) or dependent variable directly (dfilm-growth-model):  $\frac{d}{dt} d_{film} = \frac{5.5 \times 10^{-6} m}{3600 s} = 1.53 \times 10^{-9} \frac{m}{s}$



Consistency of heat flux at cold wall (Point 2) **for on-off 40% RH on warm side (Point 4):**

Condensing ( $t_1 = 1.45 \text{ h}$ ):

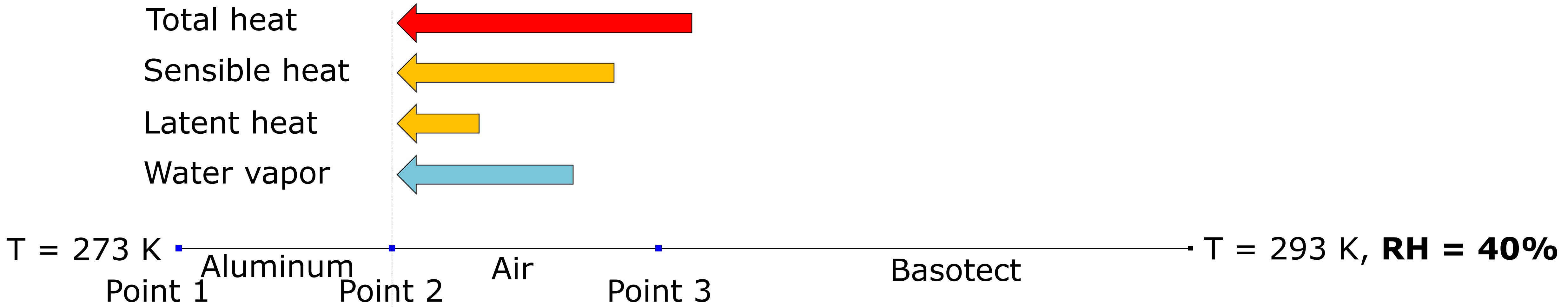
- $\nabla T = 850 \frac{\text{K}}{\text{m}} \rightarrow q_{sens} = -k \cdot \nabla T = -19.6 \frac{\text{W}}{\text{m}^2}$
- Total heat flux reported at point 2:  $q_{tot} = -23.8 \frac{\text{W}}{\text{m}^2}$
- Latent heat flux:  $q_{lat} = q_{tot} - q_{sens} = -4.2 \frac{\text{W}}{\text{m}^2}$ , in negative x-direction, released at Point 2 (as vapor cannot penetrate Aluminum)
- Latent heat release expected from growth of water film:  $q_{lat,exp} = \frac{d}{dt} d_{film} \cdot \rho_w \cdot L_v = 3.5 \frac{\text{W}}{\text{m}^2}$

Evaporating: ( $t_2 = 2.15 \text{ h}$ ):

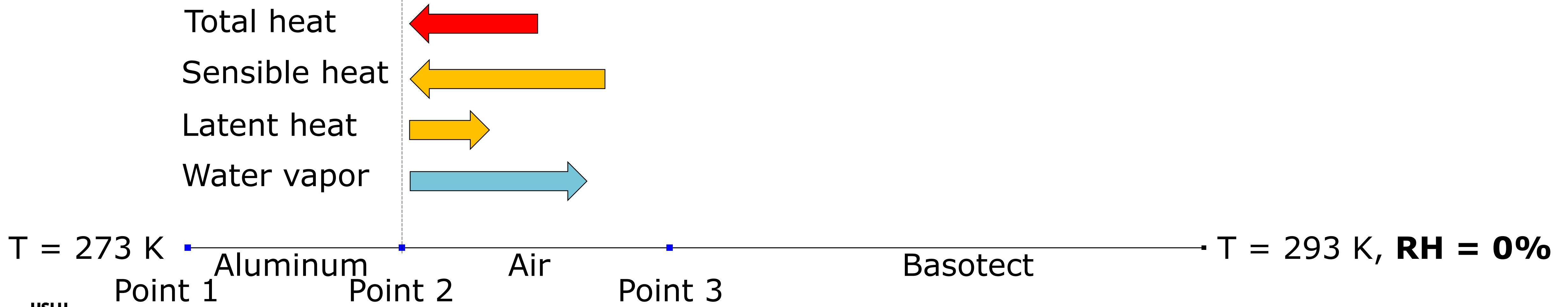
- $\nabla T = 670 \frac{K}{m} \rightarrow q_{sens} = -k \cdot \nabla T = -15.4 \frac{W}{m^2}$
- Total heat flux reported at point 2:  $q_{tot} = -10.5 \frac{W}{m^2}$
- Latent heat flux:  $q_{lat} = q_{tot} - q_{sens} = +4.9 \frac{W}{m^2}$  in positive x-direction (away from cold wall)
- Latent heat release expected from growth of water film:  $q_{lat,exp} = \frac{d}{dt} d_{film} \cdot \rho_w \cdot L_v = 5.5 \frac{W}{m^2}$

Point 2	Condensing ( $t_1 = 1.45 \text{ h}$ )	Evaporating ( $t_1 = 2.15 \text{ h}$ )
$\nabla T$ air	$850 \frac{K}{m}$	$670 \frac{K}{m}$
$q_{sens} = -k \cdot \nabla T$	$-19.6 \frac{W}{m^2}$	$-15.4 \frac{W}{m^2}$
$q_{tot}$ reported	$-23.8 \frac{W}{m^2}$	$-10.5 \frac{W}{m^2}$
$-q_{lat} = -(q_{tot} - q_{sens})$	$4.2 \frac{W}{m^2}$	$-4.9 \frac{W}{m^2}$
$q_{lat,exp} = \frac{d}{dt} d_{film} \cdot \rho_w \cdot L_v$	$3.5 \frac{W}{m^2}$	$-5.5 \frac{W}{m^2}$

## Condensing ( $t_1 = 1.45 h$ )

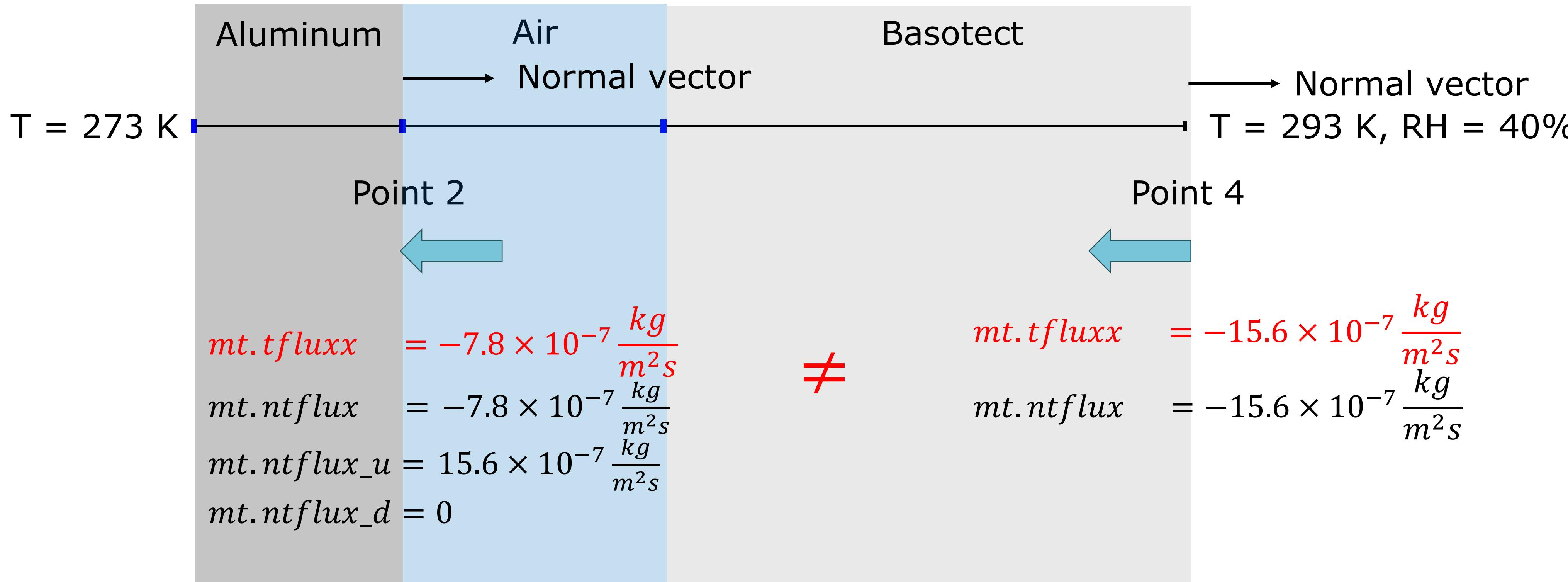


## Evaporating ( $t_2 = 2.15 h$ )



## 2. Film growth model: Using the correct vapor flux quantity

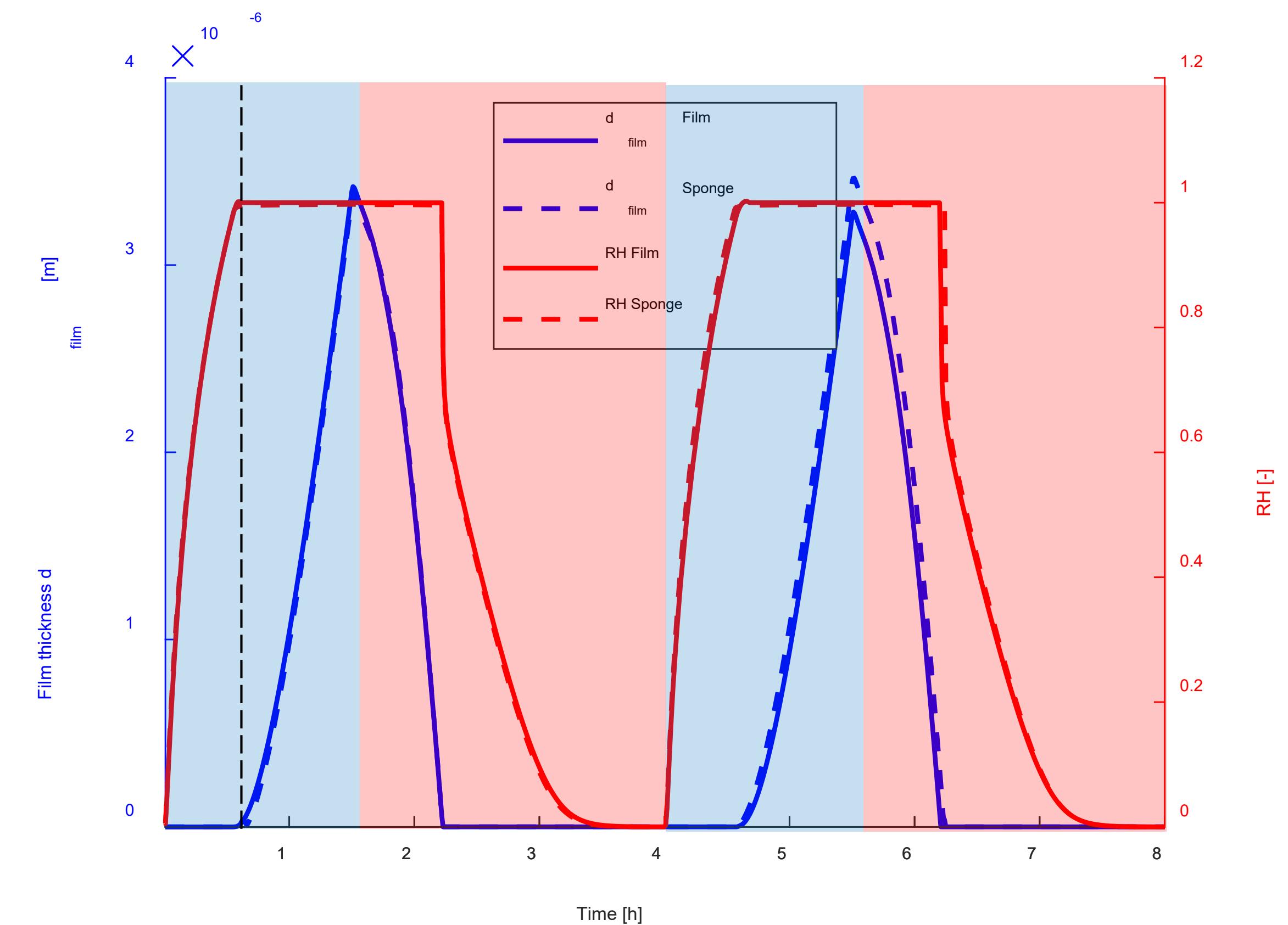
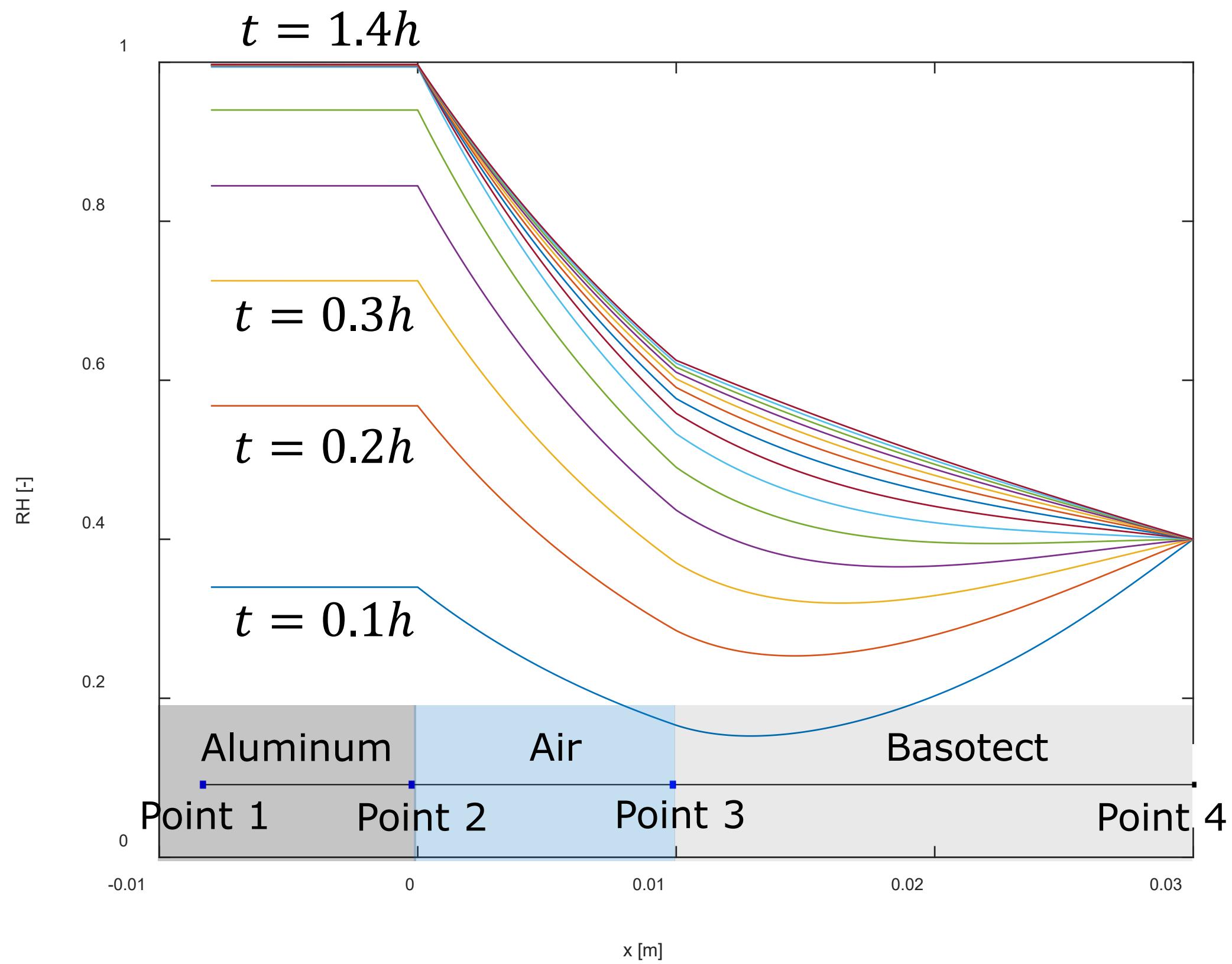
Comparison between vapor flux quantities for steady-state condensation, after 4h:



$$-\delta_p \cdot \frac{d}{dx} mt.pv = -15.7 \times 10^{-7} \frac{kg}{m^2 s}$$

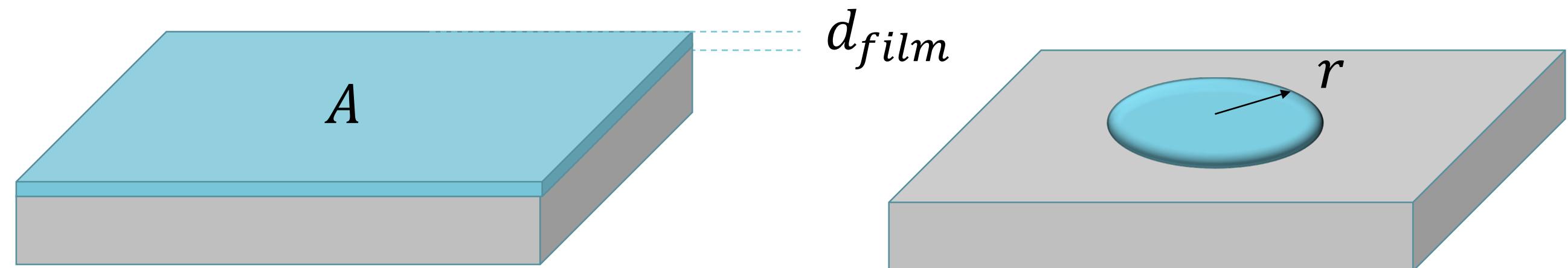
Use  $2 \cdot mt.tfluxx$  to calculate the condensing mass??

### 3. Custom built: «Sponge model»



- Good agreement between «Film model» and «Sponge model».
- Both models are able to predict the amount of water condensed on a surface.

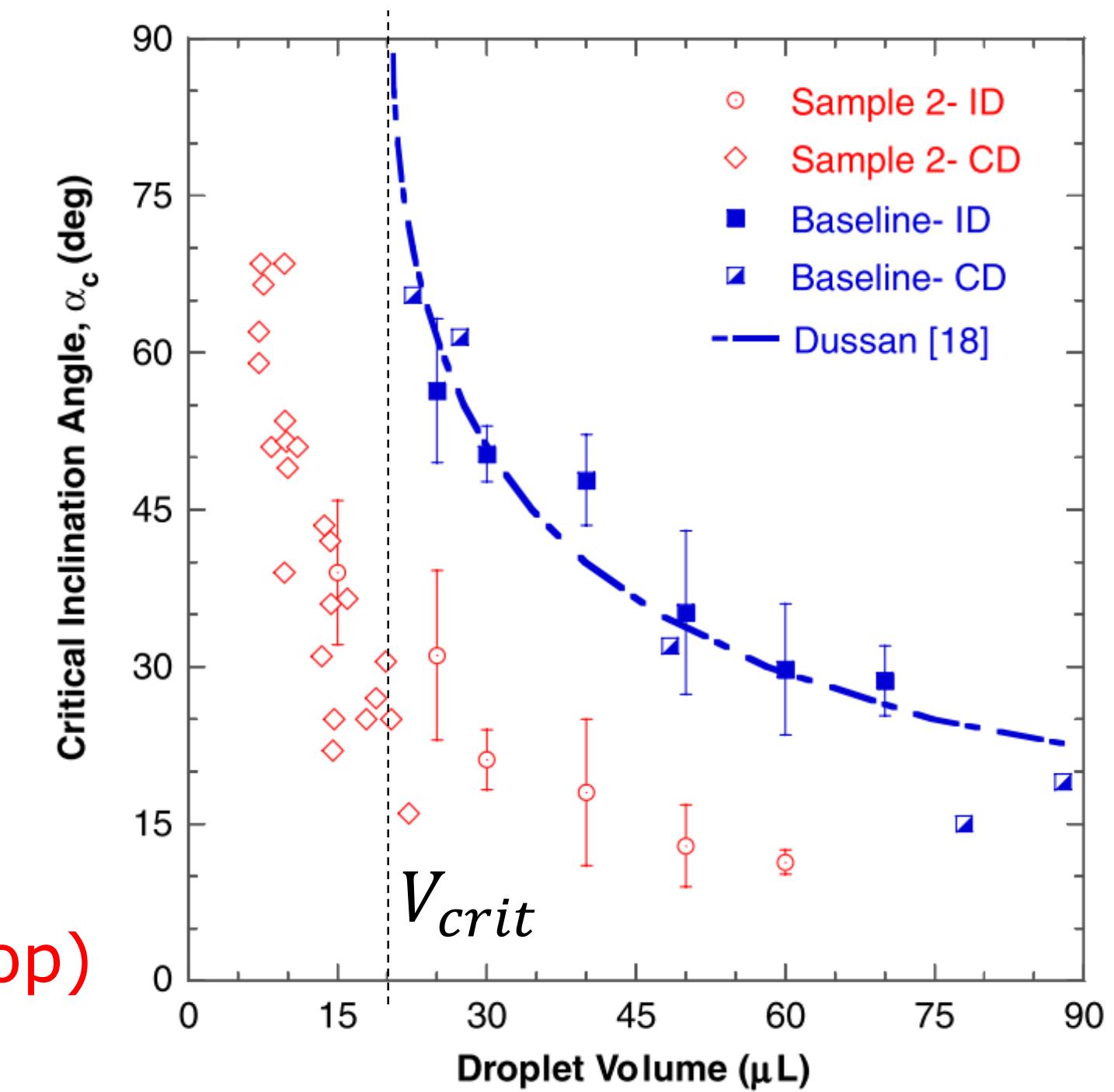
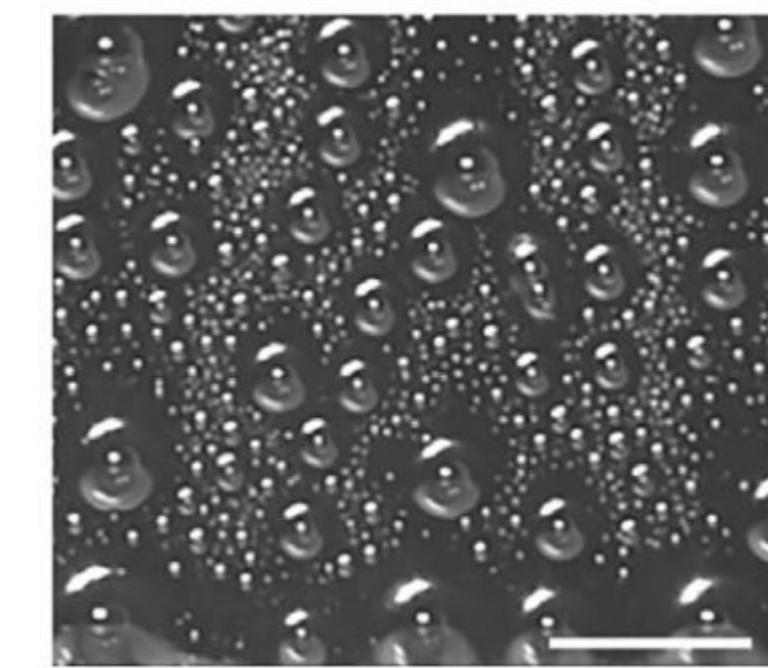
# Will running drops form?



Integrate  $d_{film}$  over surface area  $A \approx 1 \text{ cm}^2 \rightarrow$  Water volume  $V$

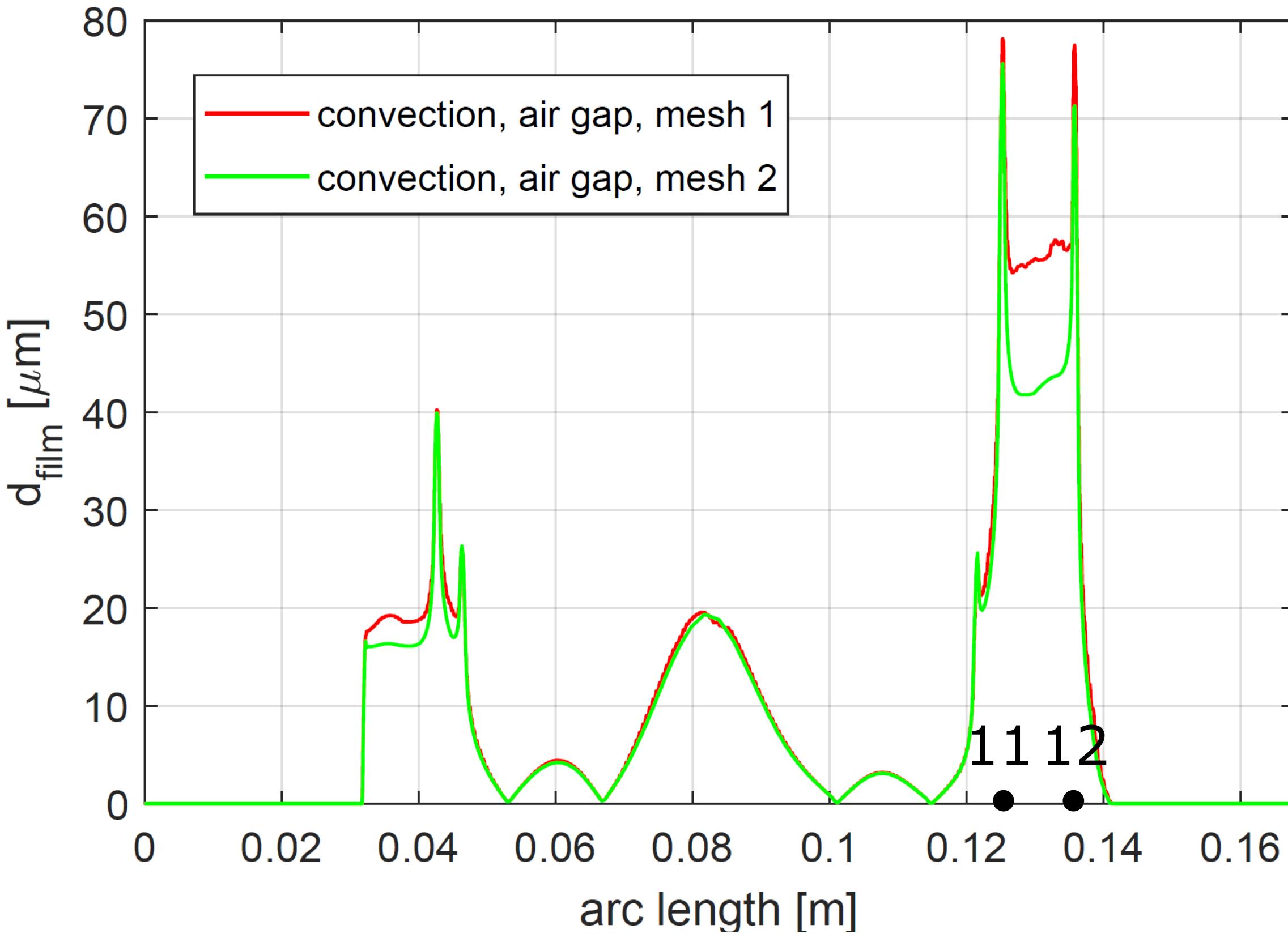
- Concentrate  $V$  in one hemispherical drop
- Compare  $V$  to critical droplet volume  $V_{crit}$  for  $90^\circ$  inclination angle (vertical wall)
- $V \geq V_{crit}$ : Running droplet
- $V < V_{crit}$ : Sessile droplet

- Running droplets predicted earlier than in reality (Concentration in 1 drop)
- But: Vibrations may reduce  $V_{crit}$
- No precise predictions are possible about the time when droplets start running off.

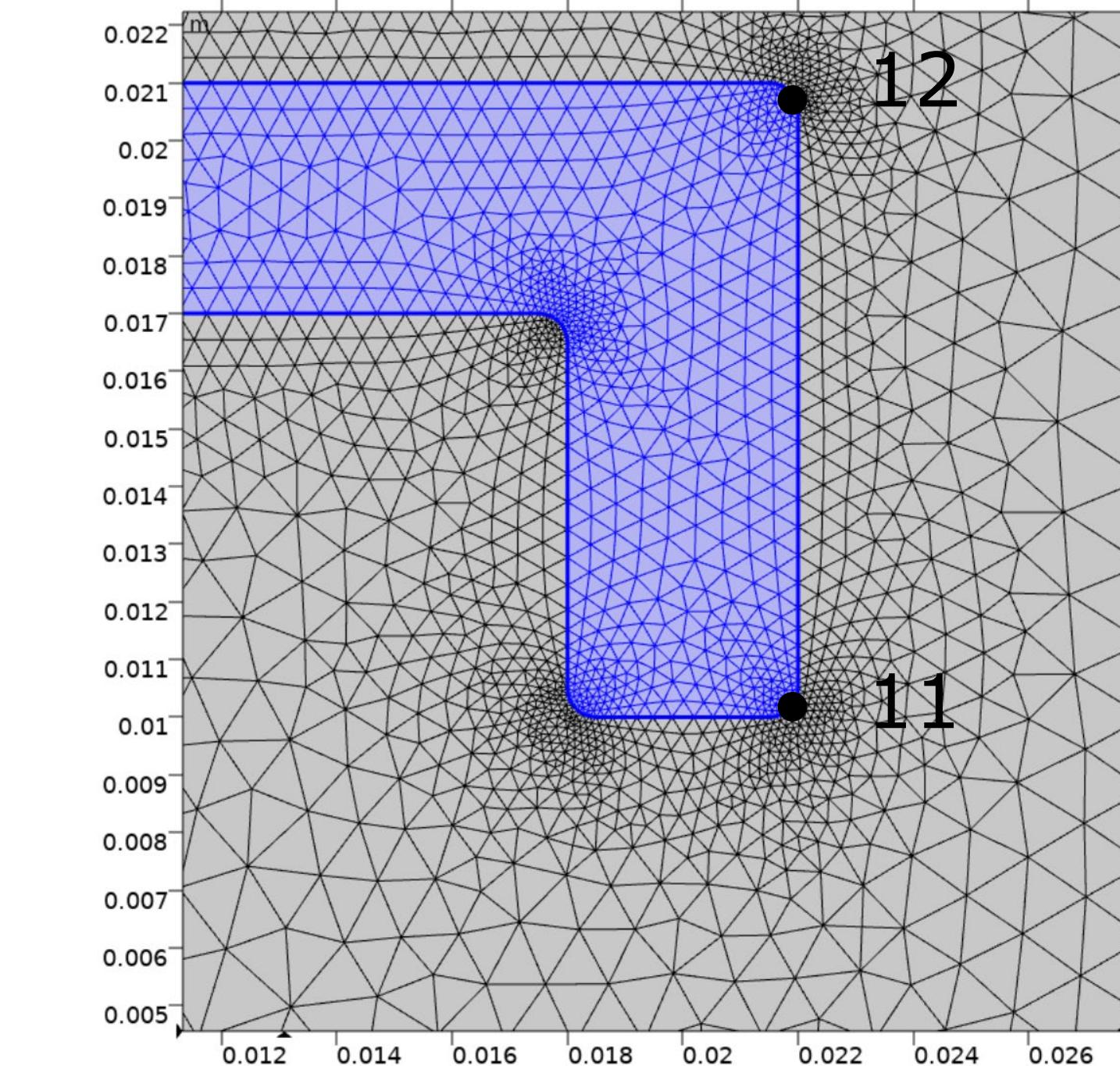


Critical inclination angle of water droplets on aluminum surface.  
Sommers et al., 2006

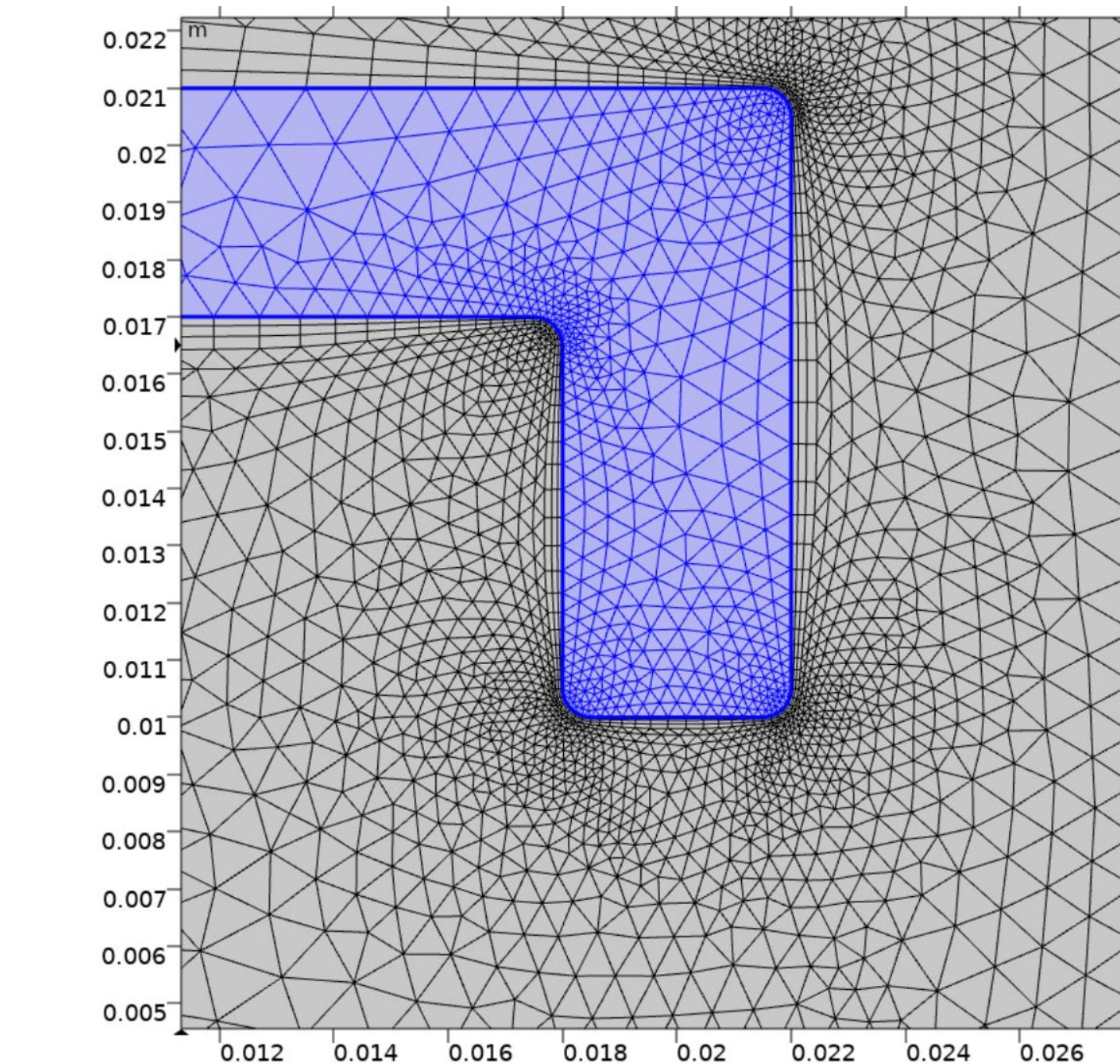
## Annex: Mesh sensitivity of dfilm for Geometry 2 (2D)



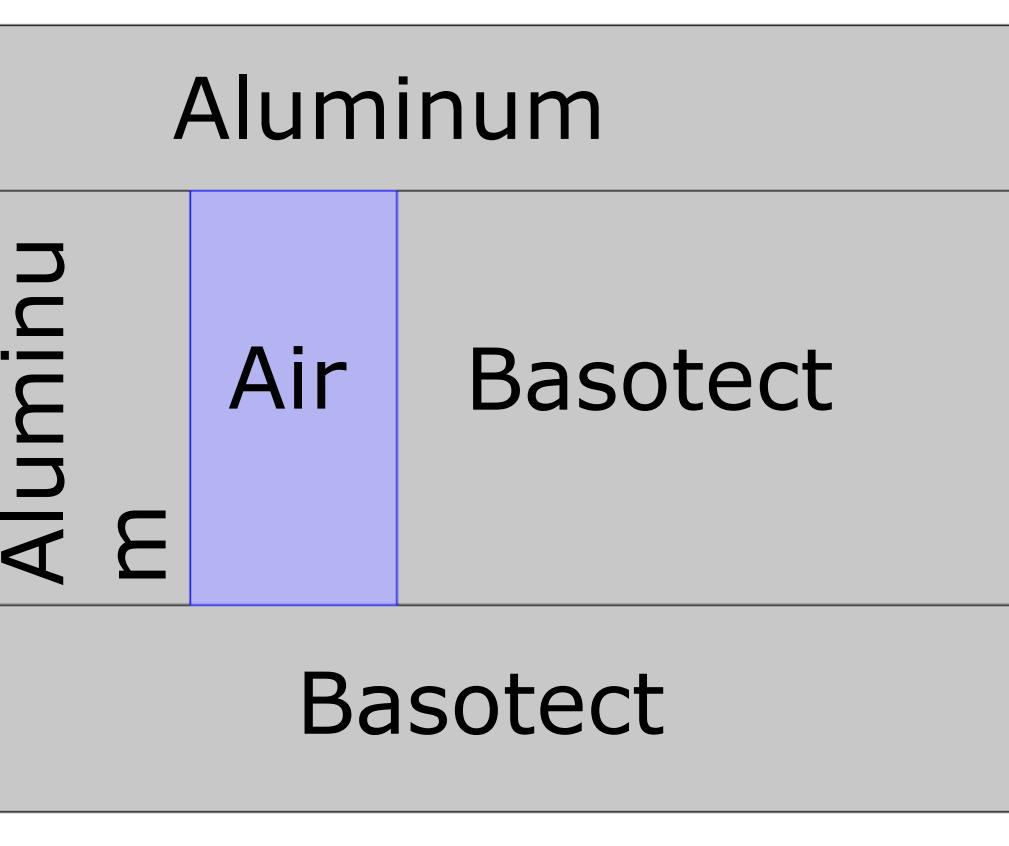
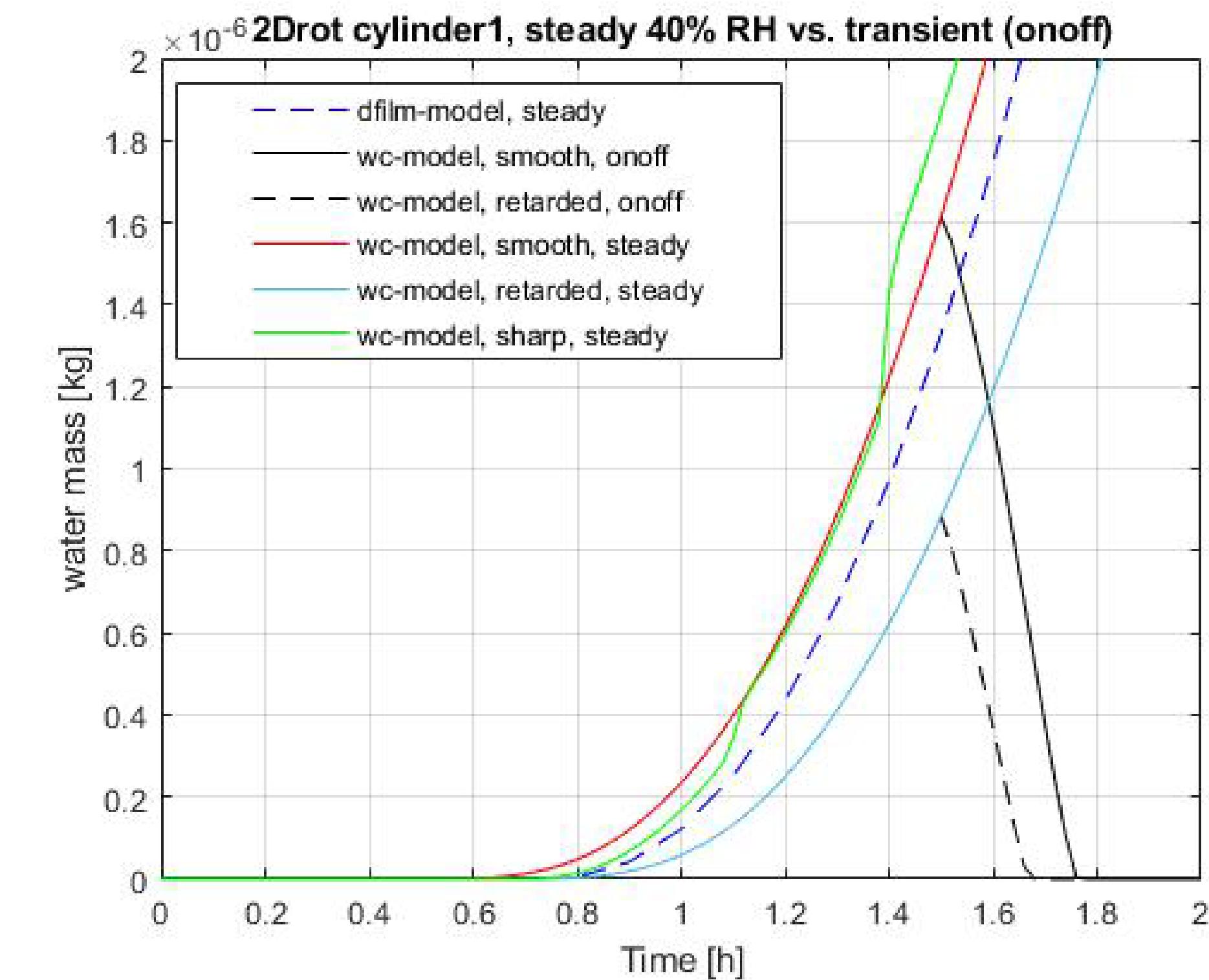
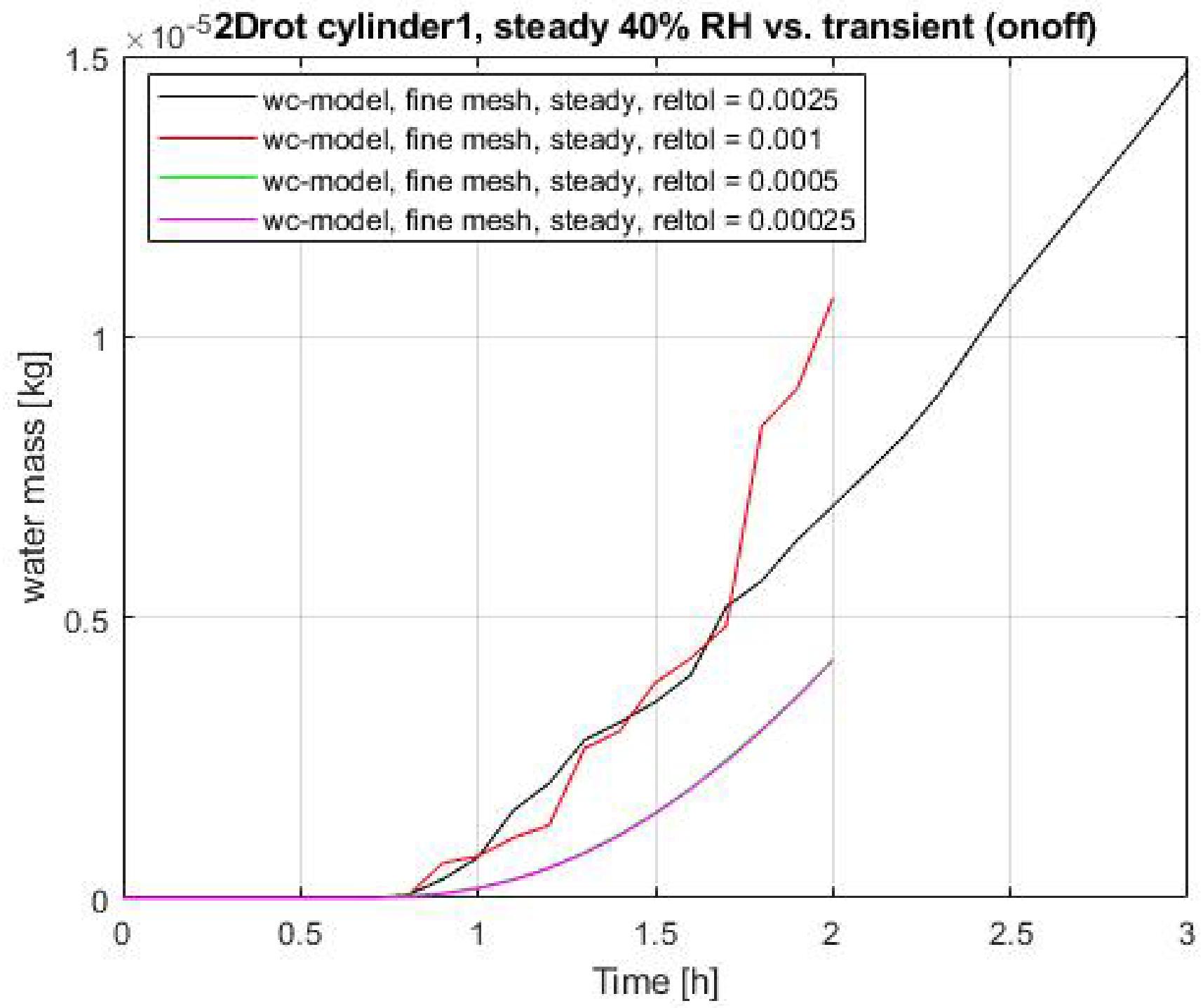
Mesh  
1



Mesh  
2

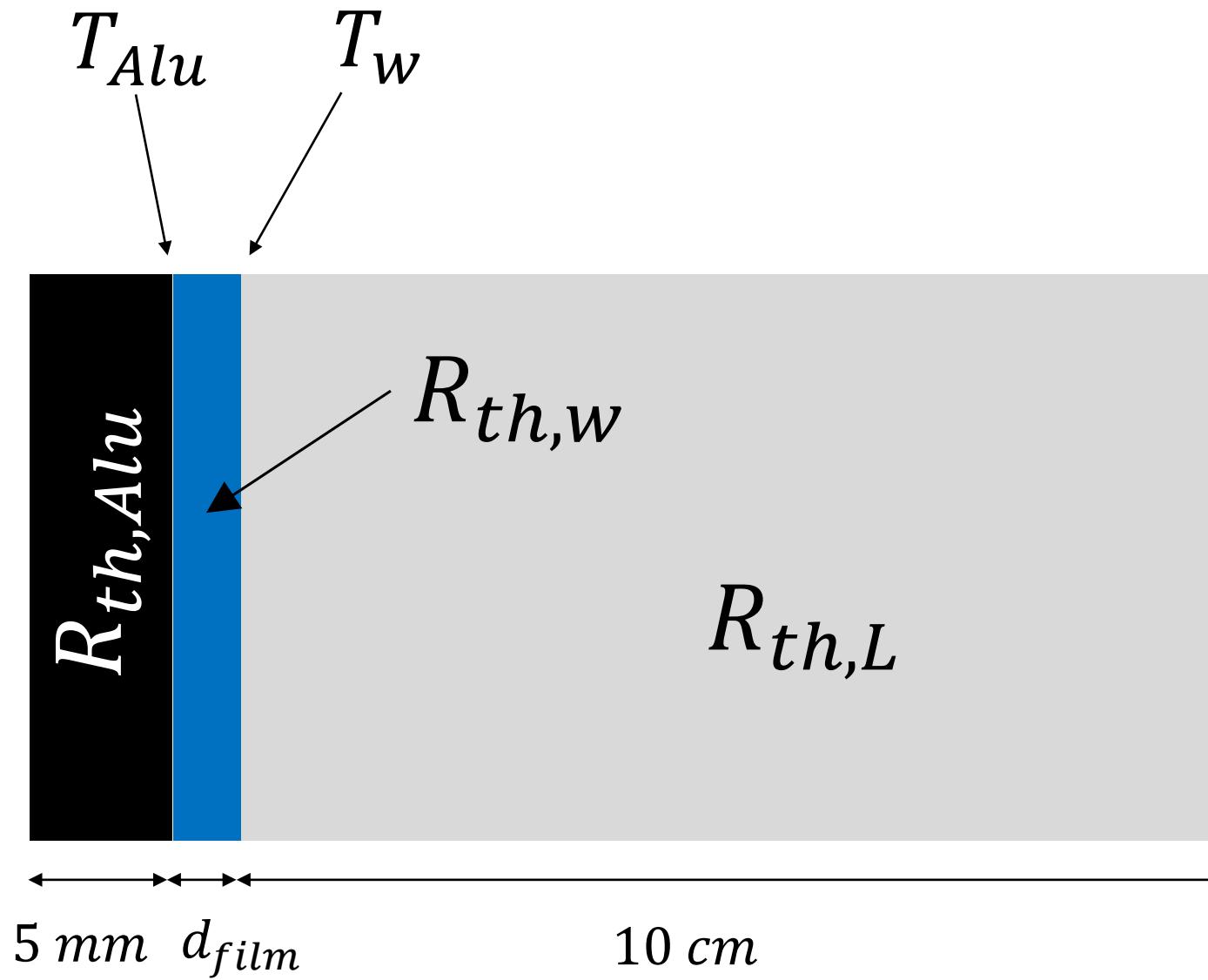


## Annex: Sponge-Model: Sensitivity to relative tolerance and $wc(\phi)$



- Wc-model: Relative tolerance 0.00025 is required, even 0.0001 if evaporation takes place
- Even with low tolerance, sharp  $wc(\phi)$  function leads to erroneous results. ( $\rightarrow$  sharp corner?)
- Smoothing  $wc(\phi)$  leads to an earlier onset of condensation compared to dfilm-model

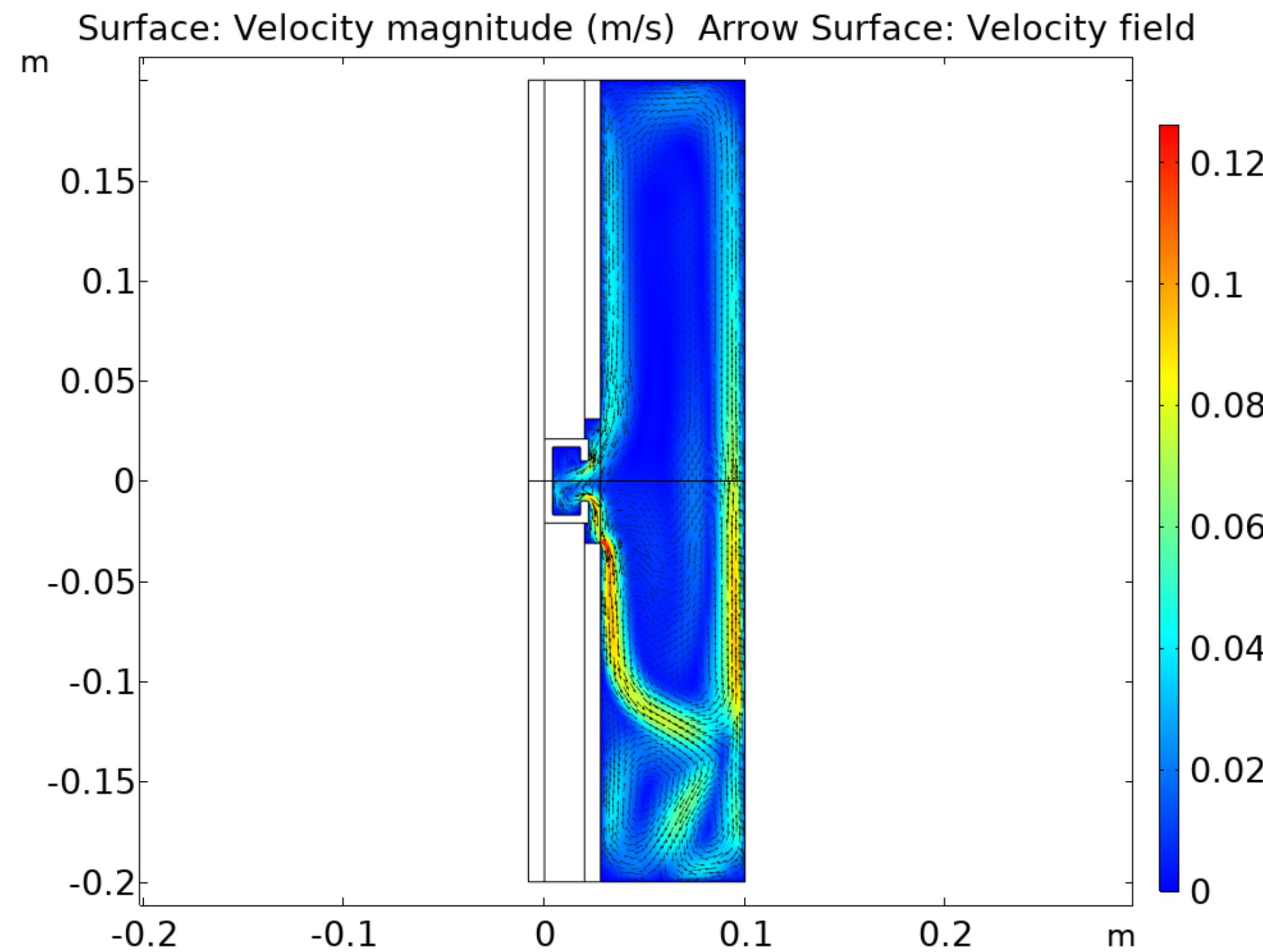
## Annex: Influence of a condensed water film on heat transport?



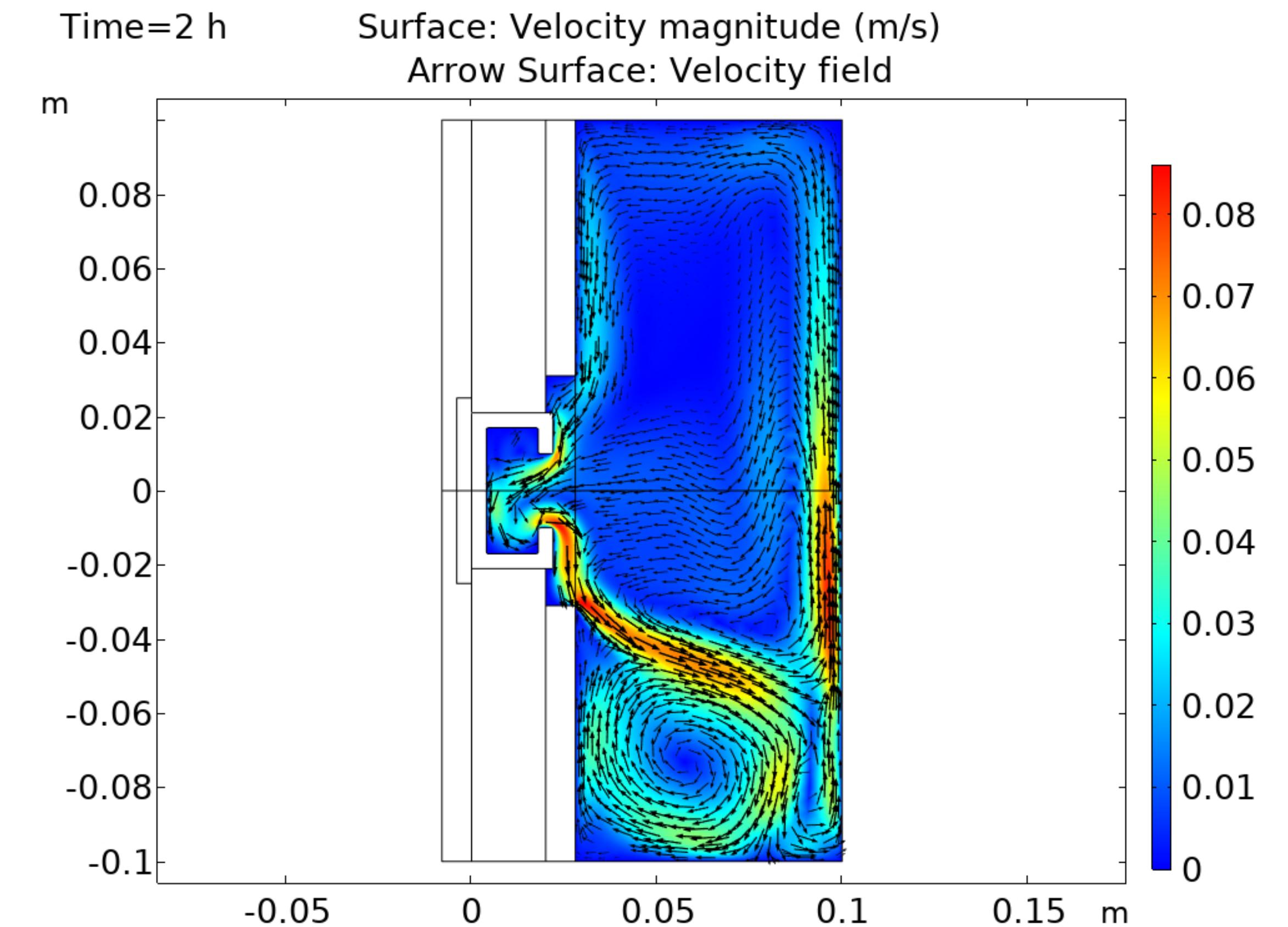
- $T_w = T_{Alu} + I_{therm} \cdot R_{th,w} > T_{Alu}$
- Model assumes  $T_w = T_{Alu} \rightarrow$  condensation rate overestimated
- $R_{th,w} \sim d_{film}$ : Temperature difference  $\Delta T = T_w - T_{Alu}$  increases with increasing  $d_{film}$ 
  - $\Delta T \approx 1 K$  for  $d_{film} \approx 1 mm$
- Most simulated  $d_{film}$  are on the order max. 0.1 mm

→ Most simulated water films are thin enough that  $T_w = T_{Alu}$  is a valid assumption.

## Annex: Sensitivity of dfilm to vertical length for Geometry 2 (2D)

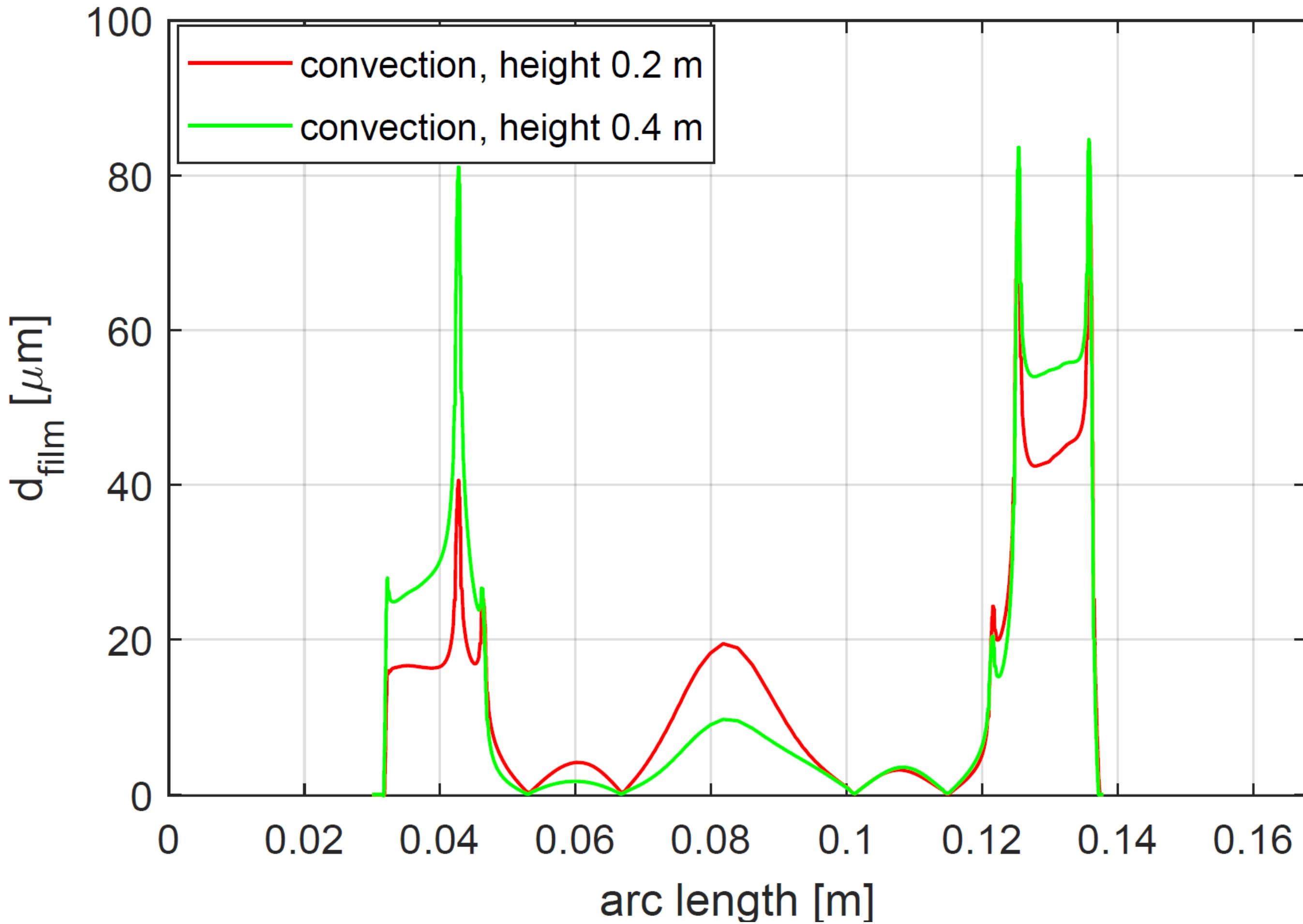


0.4 m vertical length: Max. downward velocity 13 cm/s

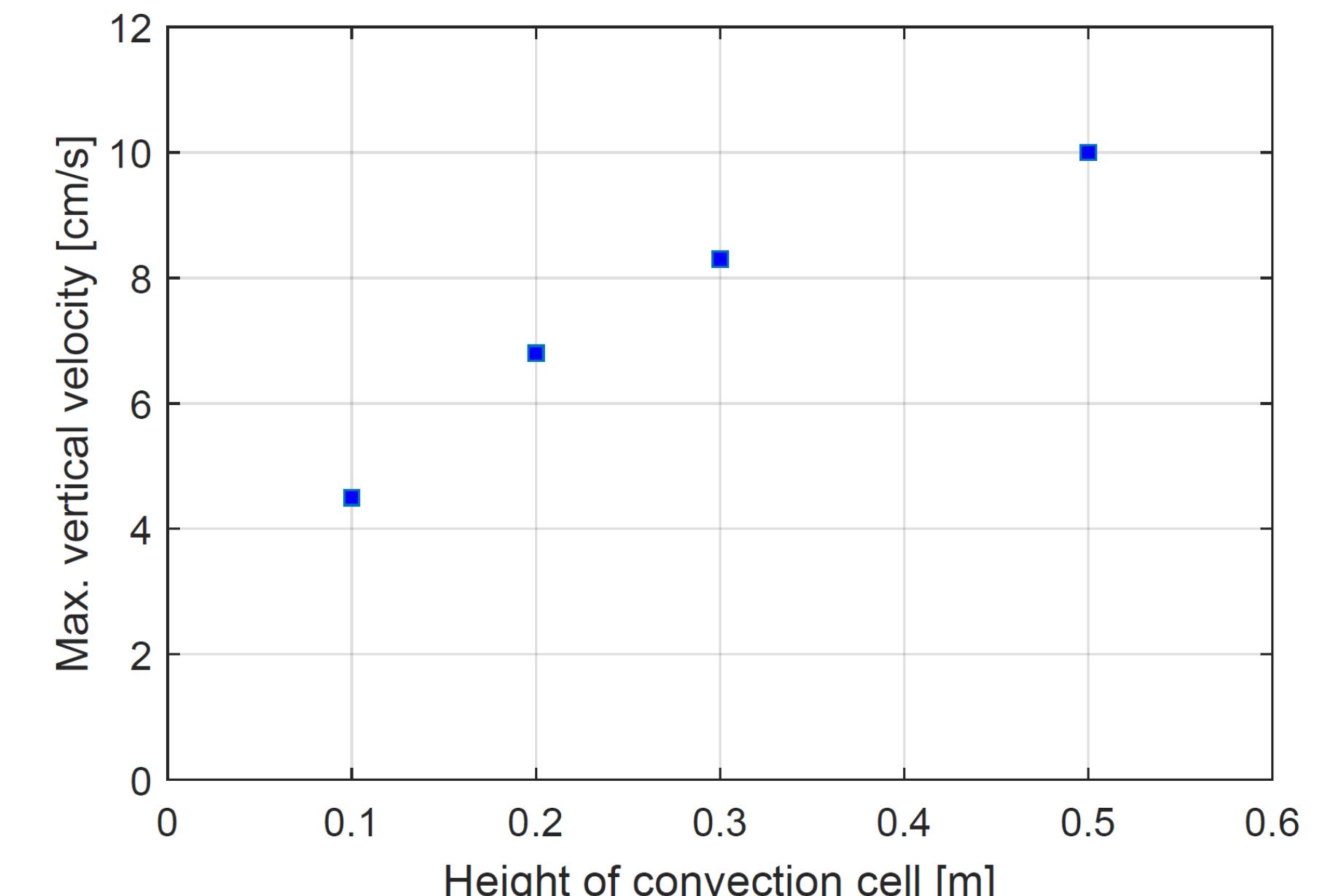


0.2 m vertical length: Max. downward velocity 10.5 cm/s

## Annex: Sensitivity of dfilm to vertical length for Geometry 2 (2D)



Sensitivity of max. vertical velocity to vertical length in rectangular, homogeneous test cell ( $\Delta T = 10 \text{ K}$ ):



- Exact amount of water condensed on alu depends on size of the convection cell
- Larger cell: More condensation on protruding surfaces, less condensation within C-profile